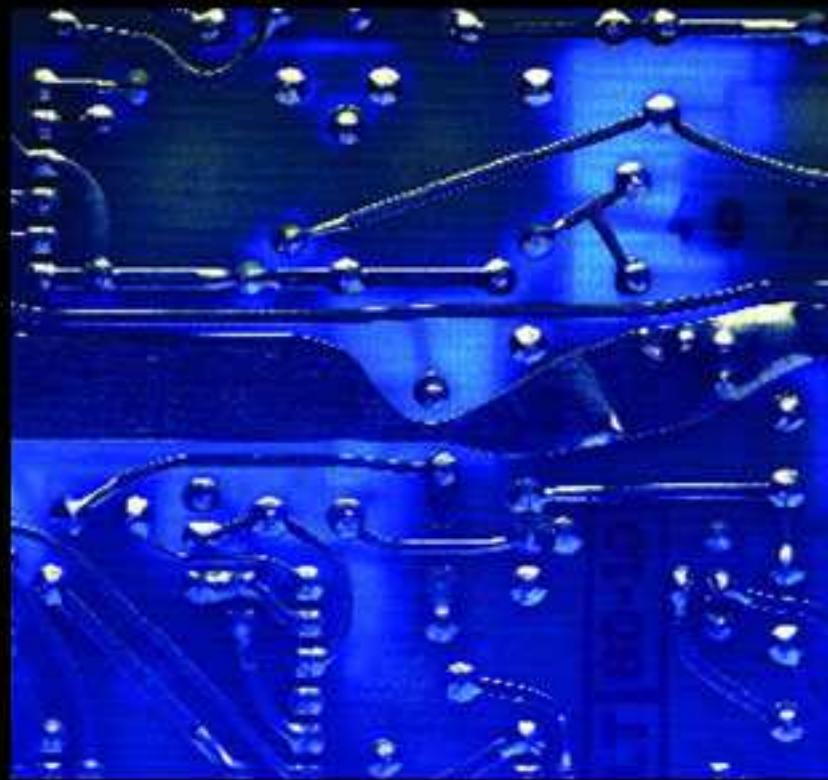


ELECTRONIC DEVICES AND CIRCUIT THEORY

TENTH EDITION

BOYLESTAD



PEARSON

Chapter 6 & 7:
Field-Effect Transistors and Applications

© Modified by Yuttapong Jirarakksopakun
ENE, KMUTT 2009

FETs vs. BJTs

Similarities:

- Amplifiers
- Switching devices
- Impedance matching circuits

Differences:

- FETs are voltage controlled devices. BJTs are current controlled devices.
- FETs have a higher input impedance. BJTs have higher gains.
- FETs are less sensitive to temperature variations and are more easily integrated on ICs.
- FETs are generally more static sensitive than BJTs.

FET Types

- **JFET:** Junction FET
- **MOSFET:** Metal–Oxide–Semiconductor FET
 - **D-MOSFET:** Depletion MOSFET
 - **E-MOSFET:** Enhancement MOSFET

JFET Construction

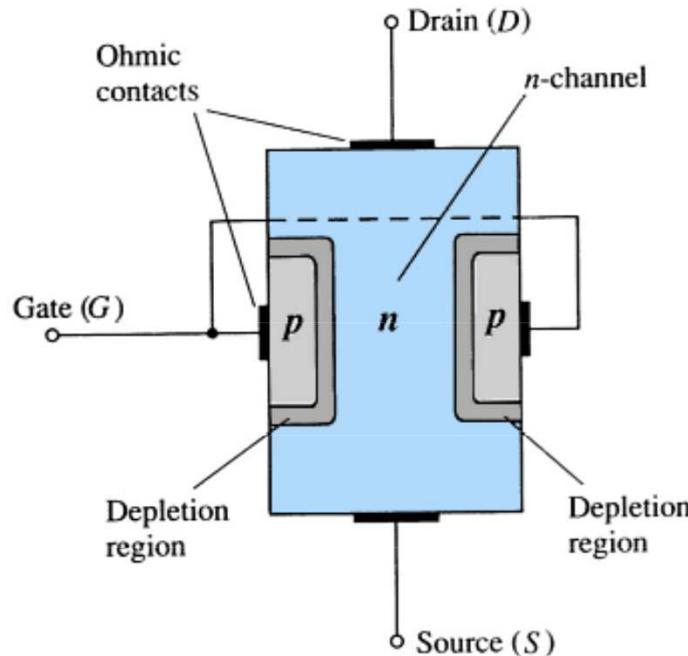
There are two types of JFETs

- n*-channel
- p*-channel

The *n*-channel is more widely used.

There are three terminals:

- Drain (D)** and **Source (S)** are connected to the *n*-channel
- Gate (G)** is connected to the *p*-type material



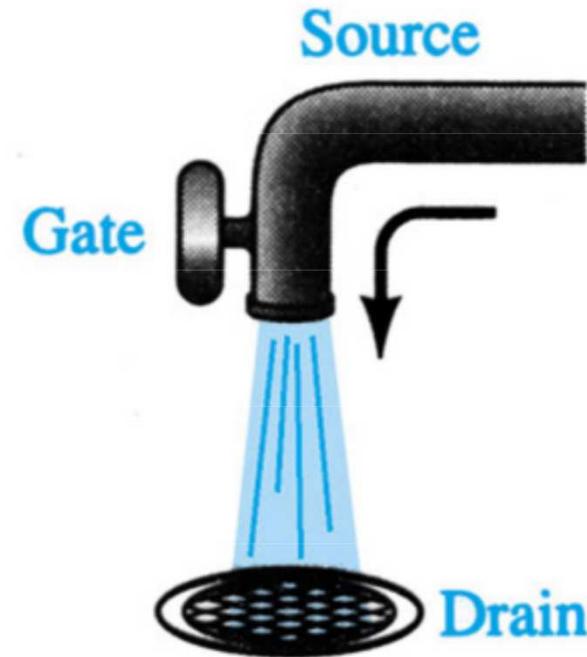
JFET Operation: The Basic Idea

JFET operation can be compared to a water spigot.

The source of water pressure is the accumulation of electrons at the negative pole of the drain-source voltage.

The drain of water is the electron deficiency (or holes) at the positive pole of the applied voltage.

The control of flow of water is the gate voltage that controls the width of the n-channel and, therefore, the flow of charges from source to drain.



JFET Operating Characteristics

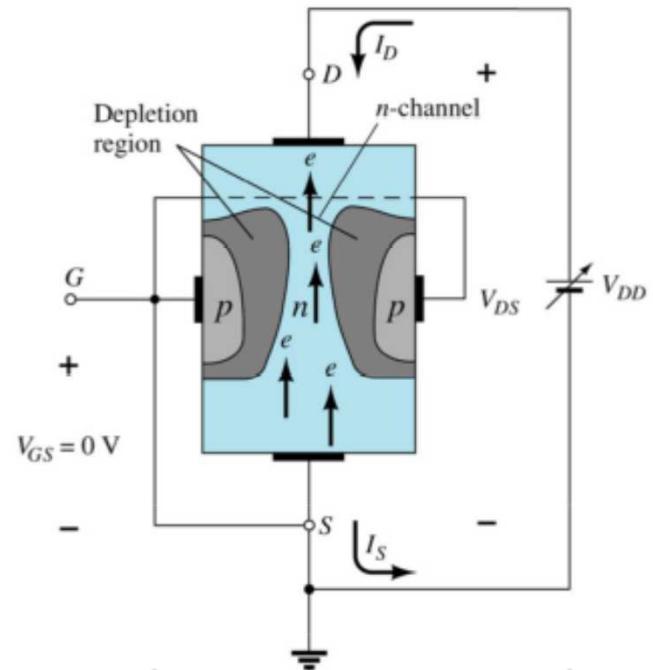
There are three basic operating conditions for a JFET:

- $V_{GS} = 0$, V_{DS} increasing to some positive value
- $V_{GS} < 0$, V_{DS} at some positive value
- Voltage-controlled resistor

JFET Operating Characteristics: $V_{GS} = 0 \text{ V}$

Three things happen when $V_{GS} = 0$ and V_{DS} is increased from 0 to a more positive voltage

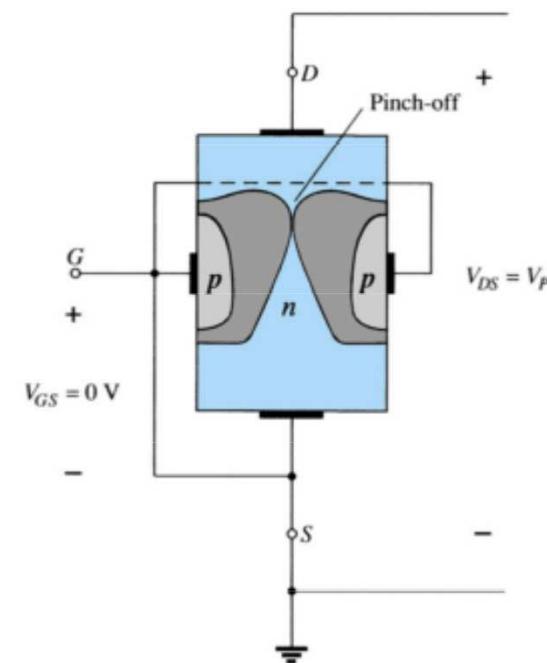
- The depletion region between p-gate and n-channel increases as electrons from n-channel combine with holes from p-gate.
- Increasing the depletion region, decreases the size of the n-channel which increases the resistance of the n-channel.
- Even though the n-channel resistance is increasing, the current (I_D) from source to drain through the n-channel is increasing. This is because V_{DS} is increasing.



JFET Operating Characteristics: Pinch Off

If $V_{GS} = 0$ and V_{DS} is further increased to a more positive voltage, then the depletion zone gets so large that it pinches off the n-channel.

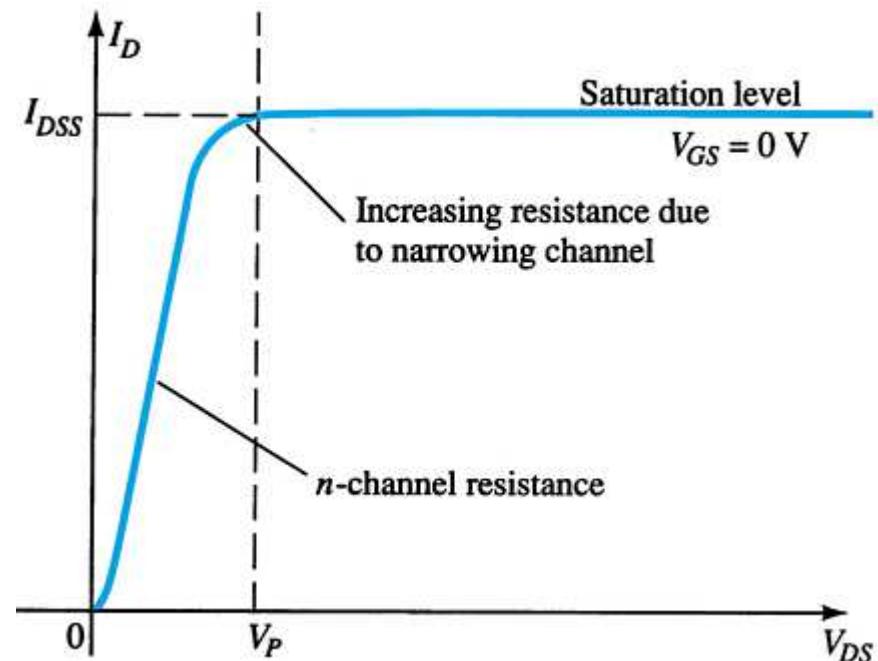
This suggests that the current in the n-channel (I_D) would drop to 0A, but it does just the opposite—as V_{DS} increases, so does I_D .



JFET Operating Characteristics: Saturation

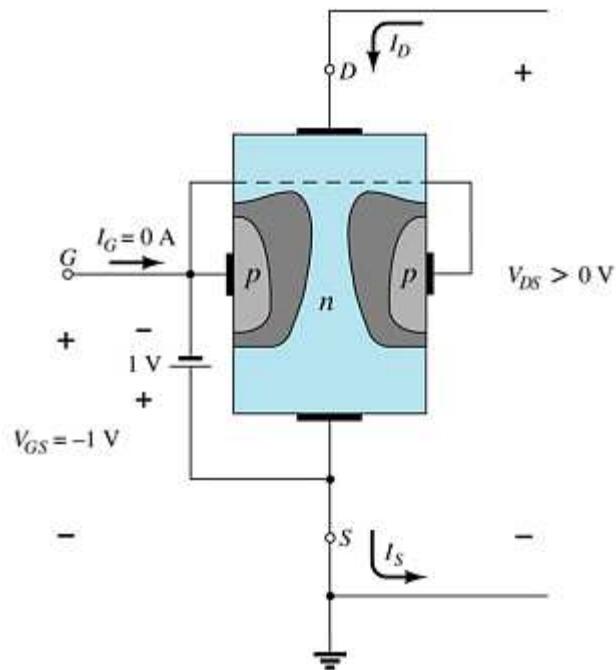
At the pinch-off point:

- Any further increase in V_{GS} does not produce any increase in I_D . V_{GS} at pinch-off is denoted as V_p .
- I_D is at saturation or maximum. It is referred to as I_{DSS} .
- The ohmic value of the channel is maximum.



JFET Operating Characteristics

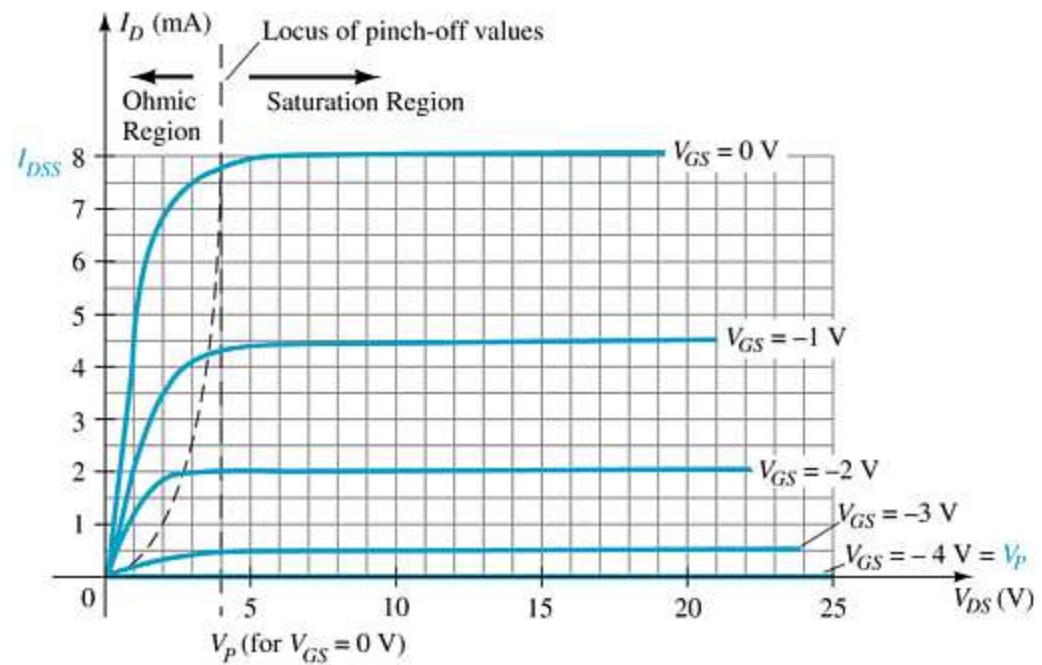
As V_{GS} becomes more negative, the depletion region increases.



JFET Operating Characteristics

As V_{GS} becomes more negative:

- The JFET experiences pinch-off at a lower voltage (V_p).
- I_D decreases ($I_D < I_{DSS}$) even though V_{DS} is increased.
- Eventually I_D reaches 0 A. V_{GS} at this point is called V_p or $V_{GS(off)}$.



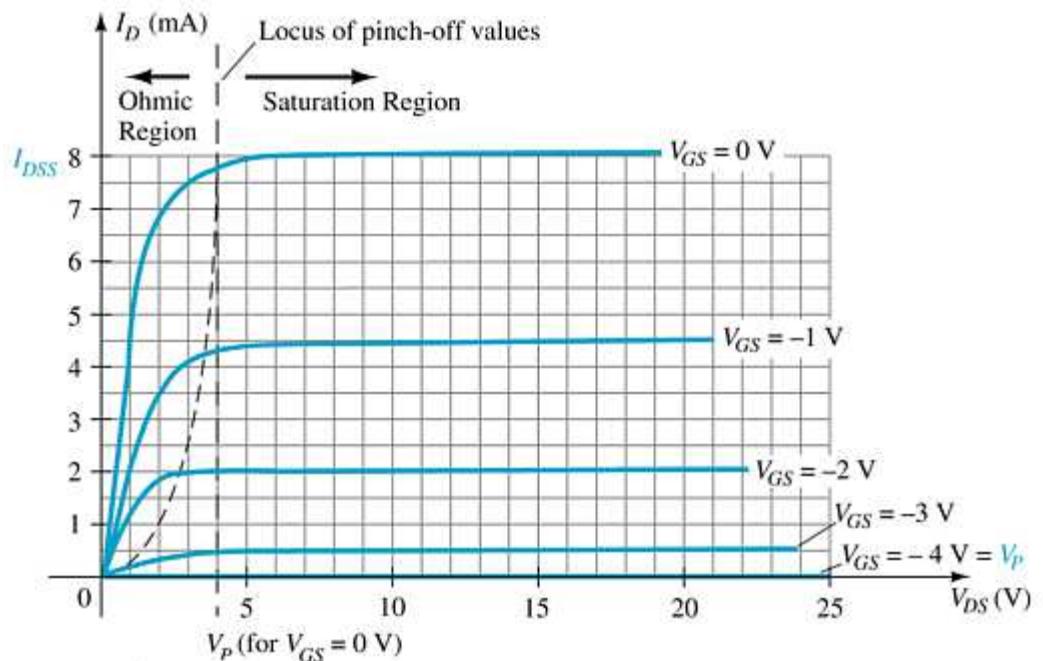
Also note that at high levels of V_{DS} the JFET reaches a breakdown situation. I_D increases uncontrollably if $V_{DS} > V_{DSmax}$.

JFET Operating Characteristics: Voltage-Controlled Resistor

The region to the left of the pinch-off point is called the ohmic region.

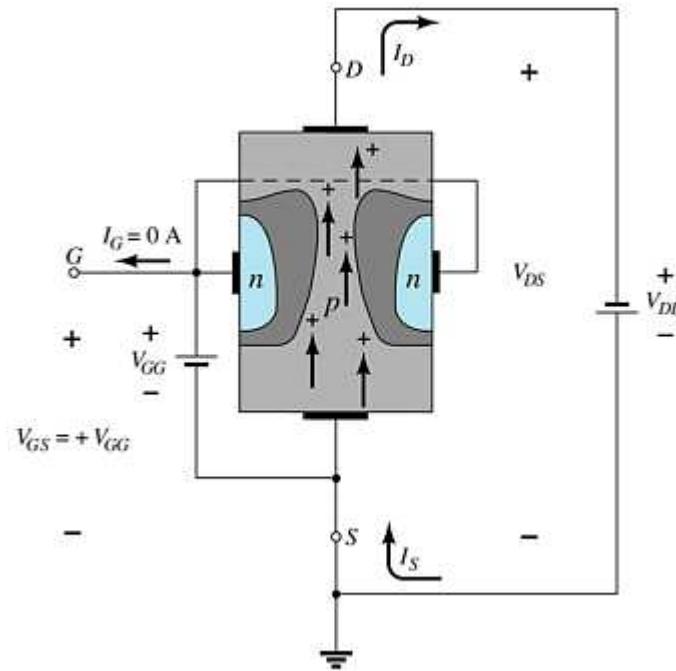
The JFET can be used as a variable resistor, where V_{GS} controls the drain-source resistance (r_d). As V_{GS} becomes more negative, the resistance (r_d) increases.

$$r_d = \frac{r_o}{\left(1 - \frac{V_{GS}}{V_P}\right)^2}$$



p-Channel JFETS

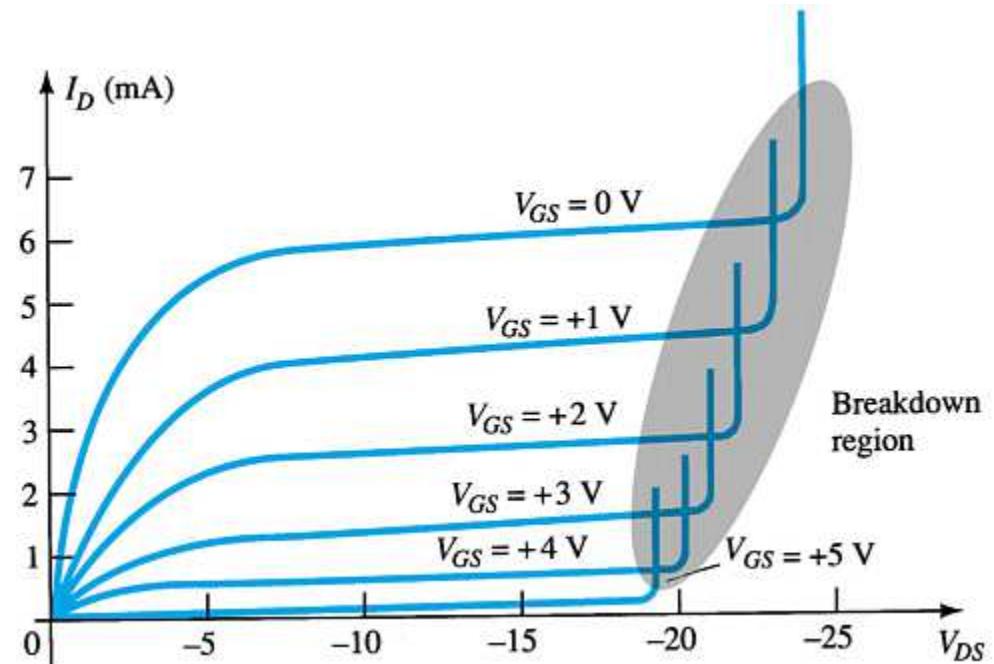
The *p*-channel JFET behaves the same as the *n*-channel JFET, except the voltage polarities and current directions are reversed.



p-Channel JFET Characteristics

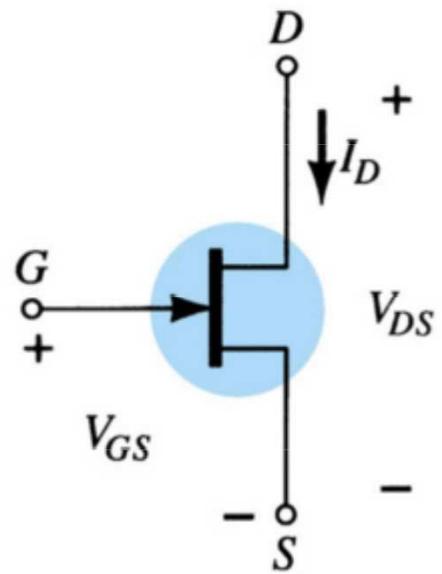
As V_{GS} increases more positively

- The depletion zone increases
- I_D decreases ($I_D < I_{DSS}$)
- Eventually $I_D = 0 \text{ A}$



Also note that at high levels of V_{DS} the JFET reaches a breakdown situation: I_D increases uncontrollably if $V_{DS} > V_{DS\max}$.

N-Channel JFET Symbol



JFET Transfer Characteristics

The transfer characteristic of input-to-output is not as straightforward in a JFET as it is in a BJT.

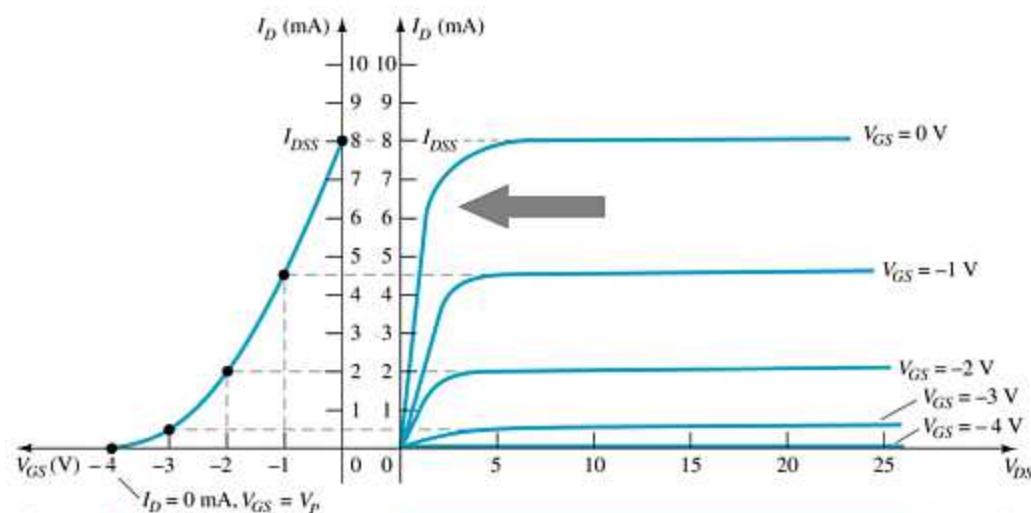
In a BJT, β indicates the relationship between I_B (input) and I_C (output).

In a JFET, the relationship of V_{GS} (input) and I_D (output) is a little more complicated:

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

JFET Transfer Curve

This graph shows the value of I_D for a given value of V_{GS} .



Plotting the JFET Transfer Curve

Using I_{DSS} and V_p ($V_{GS(off)}$) values found in a specification sheet, the transfer curve can be plotted according to these three steps:

Step 1

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

Solving for $V_{GS} = 0V$

$$I_D = I_{DSS}$$

Step 2

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

Solving for $V_{GS} = V_p$ ($V_{GS(off)}$) $I_D = 0A$

Step 3

$$\text{Solving for } V_{GS} = 0V \text{ to } V_p \quad I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$



JFET Specifications Sheet

Electrical Characteristics

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------|--------|-----|-----|-----|------|
|----------------|--------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | |
|--|---------------|------|------|--------------|------|
| Gate-Source Breakdown Voltage ($I_G = -10 \mu\text{Adc}$, $V_{DS} = 0$) | $V_{(BR)GSS}$ | -25 | - | - | Vdc |
| Gate Reverse Current ($V_{GS} = -15 \text{ Vdc}$, $V_{DS} = 0$) ($V_{GS} = -15 \text{ Vdc}$, $V_{DS} = 0$, $T_A = 100^\circ\text{C}$) | I_{GSS} | - | - | -1.0 -200 | nAdc |
| Gate Source Cutoff Voltage ($V_{DS} = 15 \text{ Vdc}$, $I_D = 10 \text{ nAdc}$) | $V_{GS(off)}$ | -0.5 | - | -6.0 | Vdc |
| Gate Source Voltage ($V_{DS} = 15 \text{ Vdc}$, $I_D = 100 \mu\text{Adc}$) | V_{GS} | - | -2.5 | - | Vdc |

ON CHARACTERISTICS

| | | | | | |
|----------------------------------|-----------|-----|-----|-----|------|
| Zero-Gate-Voltage Drain Current* | I_{DSS} | 1.0 | 3.0 | 5.0 | mAdc |
|----------------------------------|-----------|-----|-----|-----|------|

SMALL-SIGNAL CHARACTERISTICS

| | | | | | |
|--|-----------|------|-----|------|------------------|
| Forward Transfer Admittance Common Source* | y_{od} | 1000 | - | 5000 | μmhos |
| ($V_{DS} = 15 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ kHz}$) | 2NS457 | | | | |
| Output Admittance Common Source* | y_{od} | - | 10 | 50 | μmhos |
| ($V_{DS} = 15 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ kHz}$) | | | | | |
| Input Capacitance | C_{iss} | - | 4.5 | 7.0 | pF |
| ($V_{DS} = 15 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$) | | | | | |
| Reverse Transfer Capacitance | C_{rss} | - | 1.5 | 3.0 | pF |
| ($V_{DS} = 15 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$) | | | | | |

*Pulse Test: Pulse Width $\leq 6.30 \text{ ms}$; Duty Cycle $\leq 10\%$

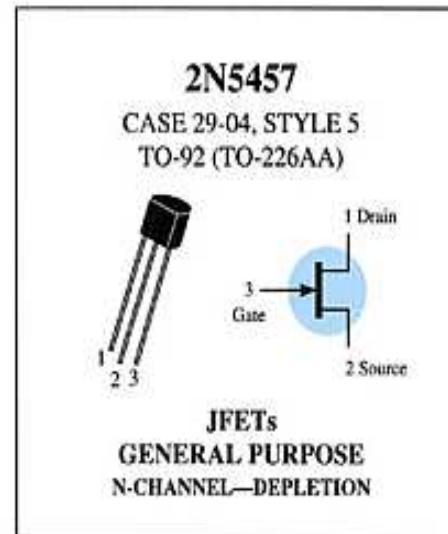


JFET Specifications Sheet

Maximum Ratings

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|-----------|-------------|----------------------------|
| Drain-Source Voltage | V_{DS} | 25 | Vdc |
| Drain-Gate Voltage | V_{DG} | 25 | Vdc |
| Reverse Gate-Source Voltage | V_{GSR} | -25 | Vdc |
| Gate Current | I_G | 10 | mAdc |
| Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 310 2.82 | mW mW/ $^\circ\text{C}$ |
| Junction Temperature Range | T_J | 125 | $^\circ\text{C}$ |
| Storage Channel Temperature Range | T_{Sg} | -65 to +150 | $^\circ\text{C}$ |



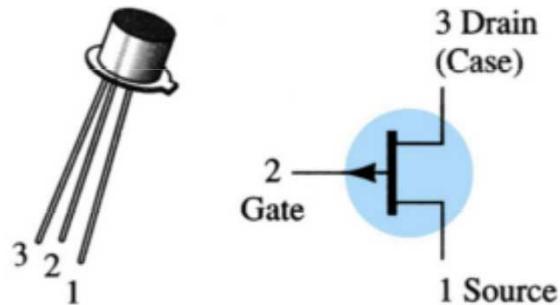
Refer to 2N4220 for graphs.

more...

Case and Terminal Identification

2N2844

CASE 22-03, STYLE 12
TO-18 (TO-206AA)



JFETs
GENERAL PURPOSE
P-CHANNEL

MOSFETs

MOSFETs have characteristics similar to JFETs and additional characteristics that make them very useful.

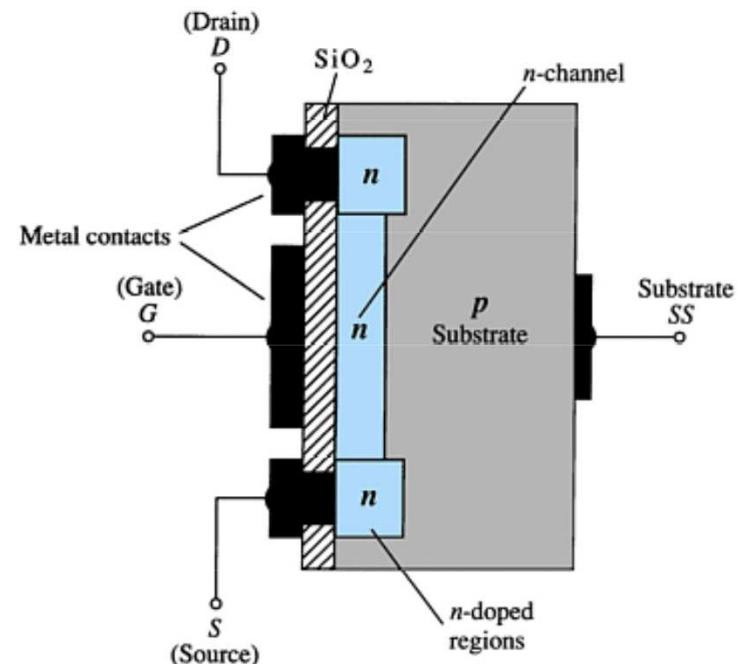
There are two types of MOSFETs:

- Depletion-Type
- Enhancement-Type

Depletion-Type MOSFET Construction

The **Drain (D)** and **Source (S)** connect to the two *n*-doped regions. These *n*-doped regions are connected via an *n*-channel. This *n*-channel is connected to the **Gate (G)** via a thin insulating layer of SiO_2 .

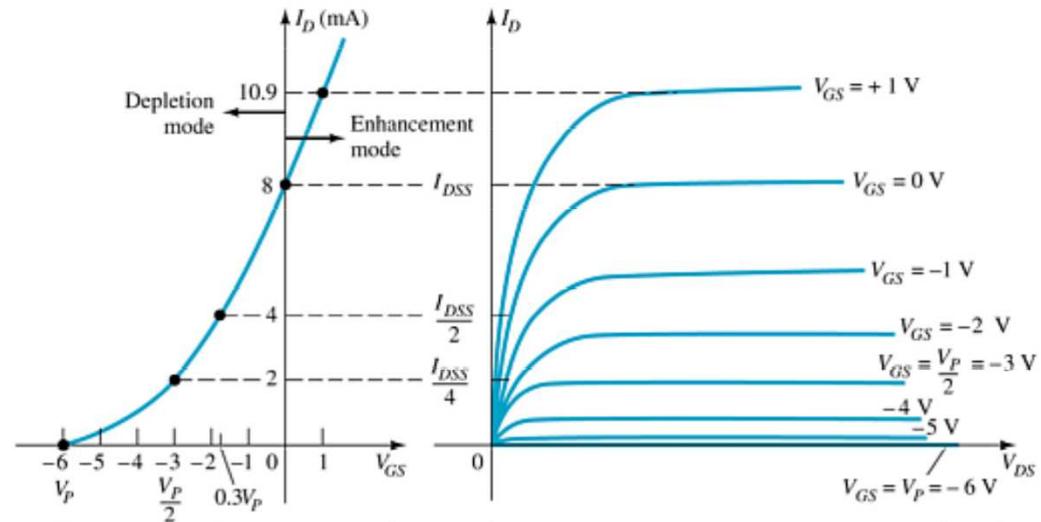
The *n*-doped material lies on a *p*-doped substrate that may have an additional terminal connection called **Substrate (SS)**.



Basic MOSFET Operation

A depletion-type MOSFET can operate in two modes:

- Depletion mode
- Enhancement mode



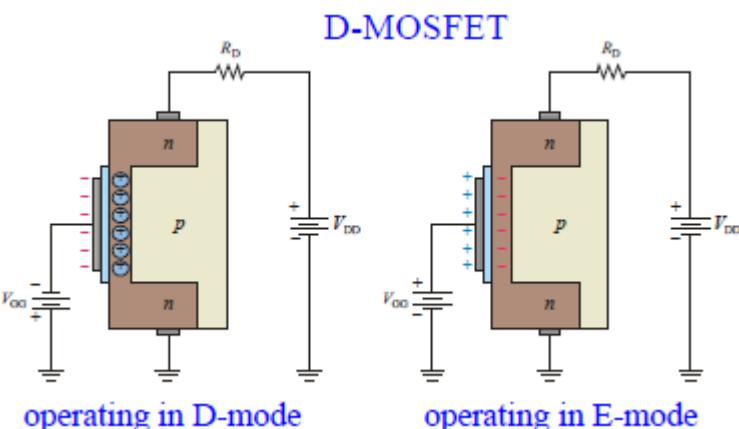
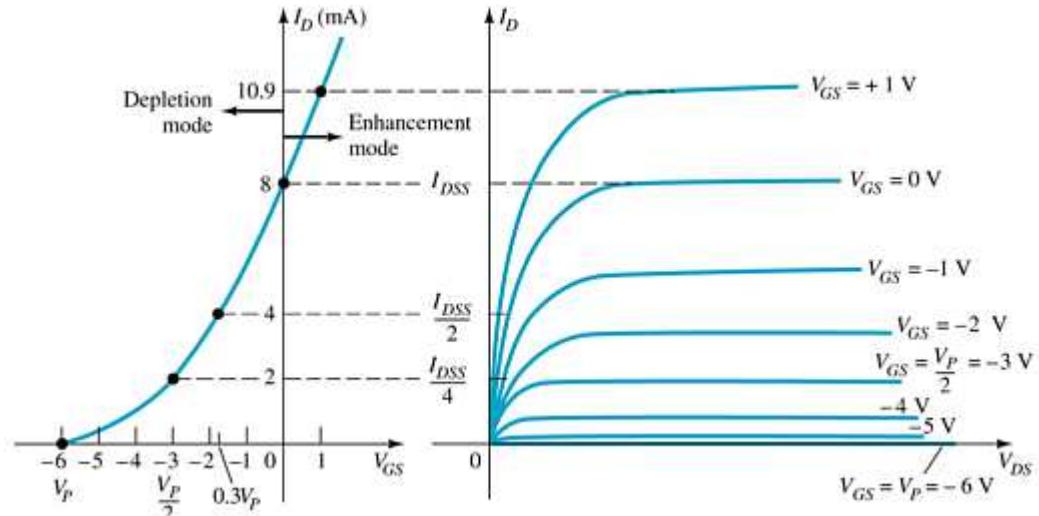
D-Type MOSFET in Depletion Mode

Depletion Mode

The characteristics are similar to a JFET.

- When $V_{GS} = 0 \text{ V}$, $I_D = I_{DSS}$
- When $V_{GS} < 0 \text{ V}$, $I_D < I_{DSS}$
- The formula used to plot the transfer curve still applies:

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

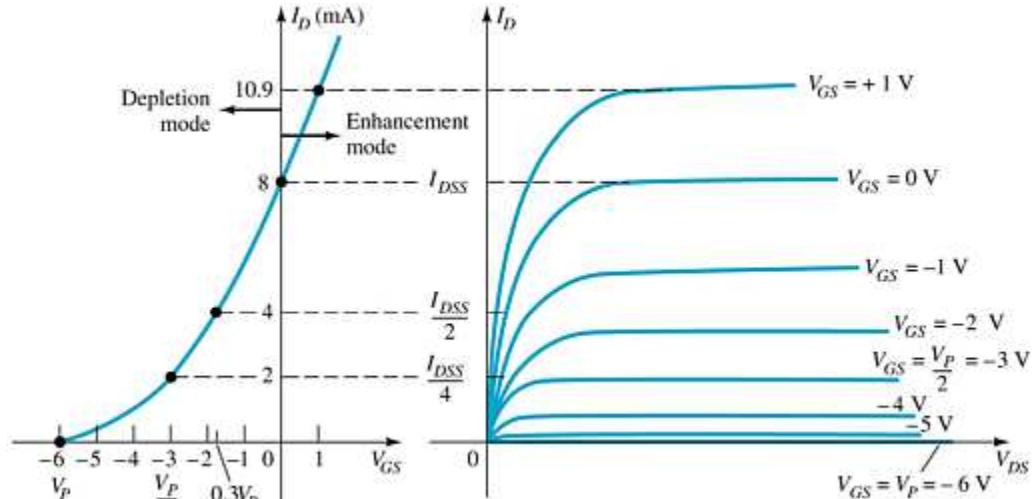


D-Type MOSFET in Enhancement Mode

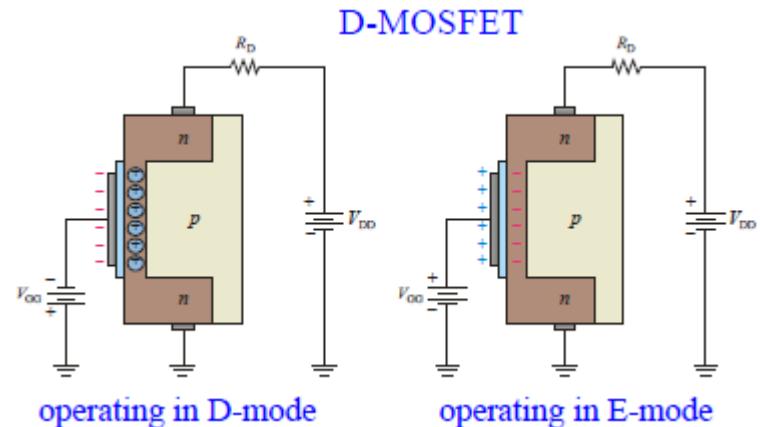
Enhancement Mode

- $V_{GS} > 0 \text{ V}$
- I_D increases above I_{DSS}
- The formula used to plot the transfer curve still applies:

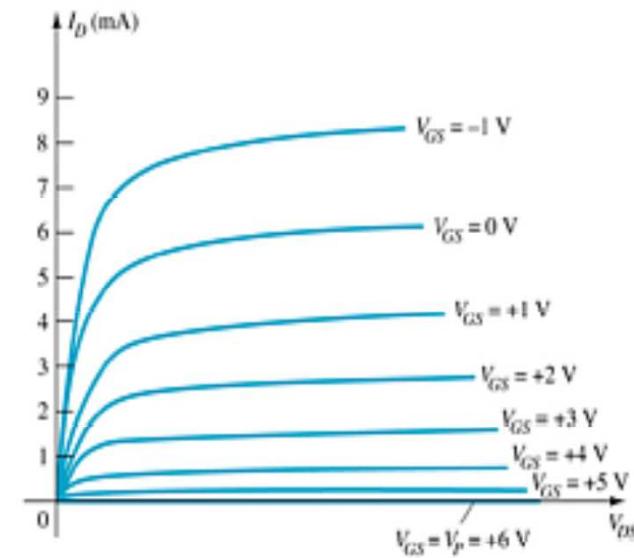
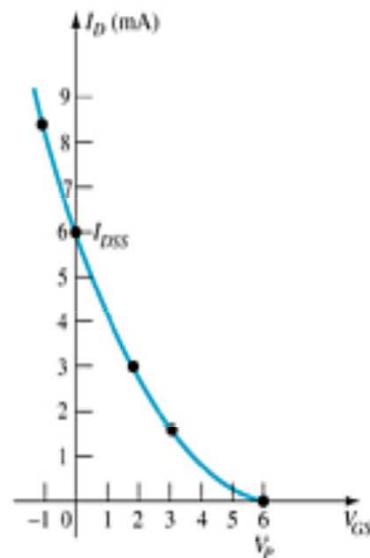
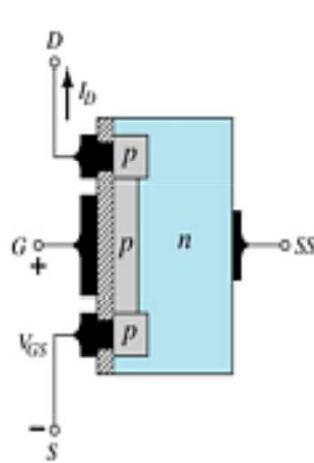
$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$



Note that V_{GS} is now a positive polarity

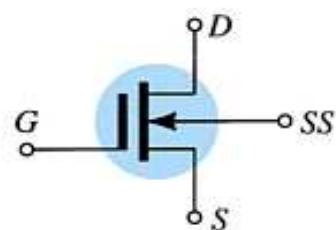


p-Channel D-Type MOSFET

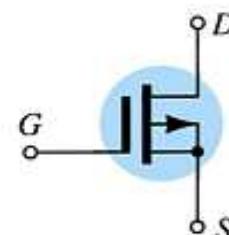
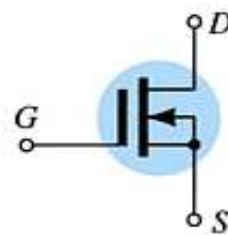
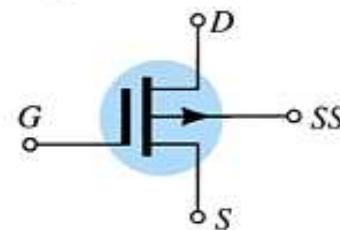


D-Type MOSFET Symbols

n-channel



p-channel



Specification Sheet

Maximum Ratings

| MAXIMUM RATINGS | | | |
|--|----------|-------------|----------------------------|
| Rating | Symbol | Value | Unit |
| Drain-Source Voltage 2N3797 | V_{DS} | 20 | Vdc |
| Gate-Source Voltage | V_{GS} | ± 10 | Vdc |
| Drain Current | I_D | 20 | mAdc |
| Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 200 1.14 | mW mW/ $^\circ\text{C}$ |
| Junction Temperature Range | T_J | +175 | $^\circ\text{C}$ |
| Storage Channel Temperature Range | T_{UG} | -65 to +200 | $^\circ\text{C}$ |



[more...](#)

Specification Sheet

Electrical Characteristics

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

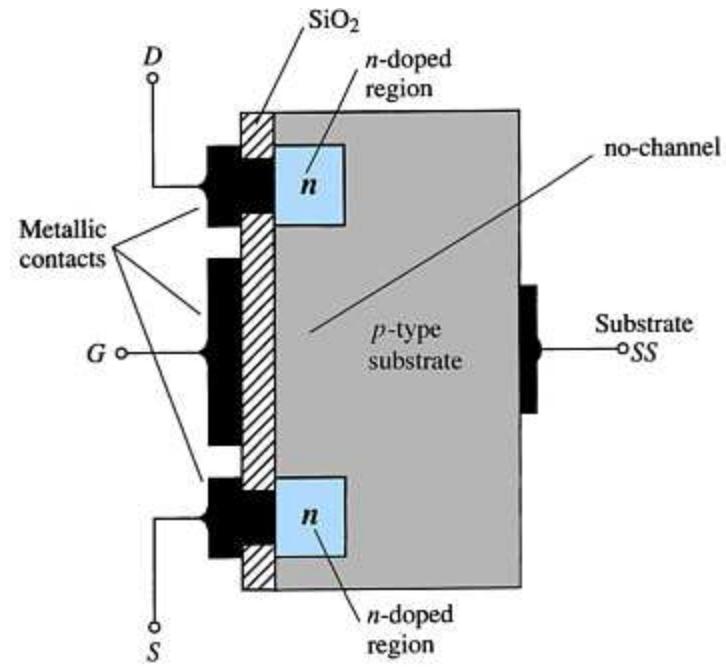
| Characteristic | Symbol | Min | Typ | Max | Unit |
|--|---------------|------|------|------------|------------------|
| OFF CHARACTERISTICS | | | | | |
| Drain Source Breakdown Voltage ($V_{GS} = -7.0 \text{ V}$, $I_D = 5.0 \mu\text{A}$) | $V_{BR(DS)}$ | 20 | 25 | — | Vdc |
| Gate Reverse Current (1) ($V_{GS} = -10 \text{ V}$, $V_{DS} = 0$) ($V_{GS} = -10 \text{ V}$, $V_{DS} = 0$, $T_A = 150^\circ\text{C}$) | I_{GS} | — | — | 1.0 200 | pAdc |
| Gate Source Cutoff Voltage ($I_D = 2.0 \mu\text{A}$, $V_{DS} = 10 \text{ V}$) | $V_{GS(off)}$ | — | -5.0 | -7.0 | Vdc |
| Drain-Gate Reverse Current (1) ($V_{DG} = 10 \text{ V}$, $I_S = 0$) | I_{DGG} | — | — | 1.0 | pAdc |
| ON CHARACTERISTICS | | | | | |
| Zero-Gate-Voltage Drain Current ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$) | $I_{DS(0)}$ | 2.0 | 2.9 | 6.0 | mAdc |
| On-State Drain Current ($V_{DS} = 10 \text{ V}$, $V_{GS} = +3.5 \text{ V}$) | $I_{DS(on)}$ | 9.0 | 14 | 18 | mAdc |
| SMALL-SIGNAL CHARACTERISTICS | | | | | |
| Forward Transfer Admittance ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1.0 \text{ kHz}$) | $ Y_{fd} $ | 1500 | 2300 | 3000 | μmhos |
| ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$) | $ Y_{fd} $ | 1500 | — | — | μmhos |
| Output Admittance ($I_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1.0 \text{ kHz}$) | $ Y_{od} $ | — | 27 | 60 | μmhos |
| Input Capacitance ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$) | C_{in} | — | 6.0 | 8.0 | pF |
| Reverse Transfer Capacitance ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$) | C_{rv} | — | 0.5 | 0.8 | pF |
| FUNCTIONAL CHARACTERISTICS | | | | | |
| Noise Figure ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1.0 \text{ kHz}$, $R_L = 3 \text{ megohms}$) | NF | — | 3.8 | — | dB |

(1) This value of current includes both the FET leakage current as well as the leakage current associated with the test socket and fixture when measured under best attainable conditions.



E-Type MOSFET Construction

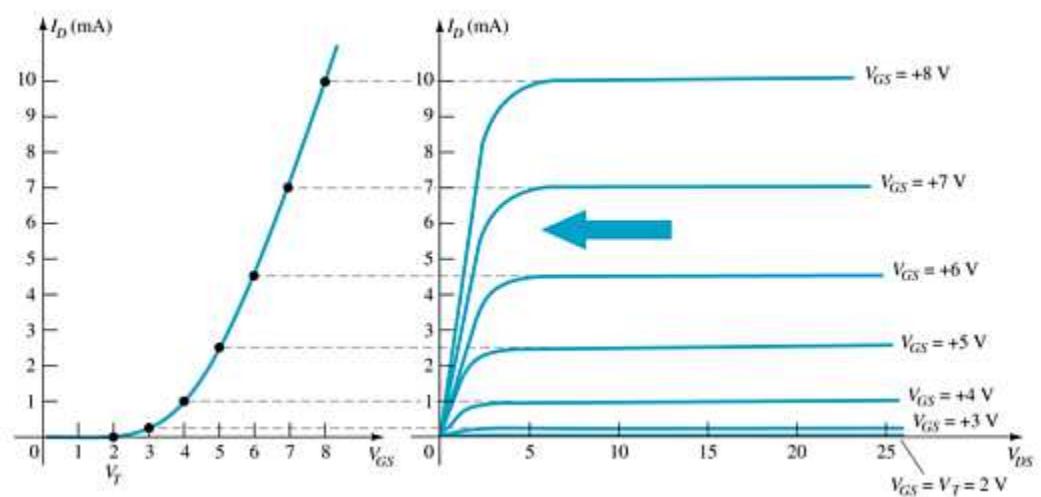
- The **Drain (D)** and **Source (S)** connect to the *n*-doped regions. These *n*-doped regions are connected via an *n*-channel
- The **Gate (G)** connects to the *p*-doped substrate via a thin insulating layer of SiO_2
- There is no channel
- The *n*-doped material lies on a *p*-doped substrate that may have an additional terminal connection called the **Substrate (SS)**



Basic Operation of the E-Type MOSFET

The enhancement-type MOSFET operates only in the enhancement mode.

- V_{GS} is always positive
- As V_{GS} increases, I_D increases
- As V_{GS} is kept constant and V_{DS} is increased, then I_D saturates (I_{DSS}) and the saturation level, V_{DSsat} is reached



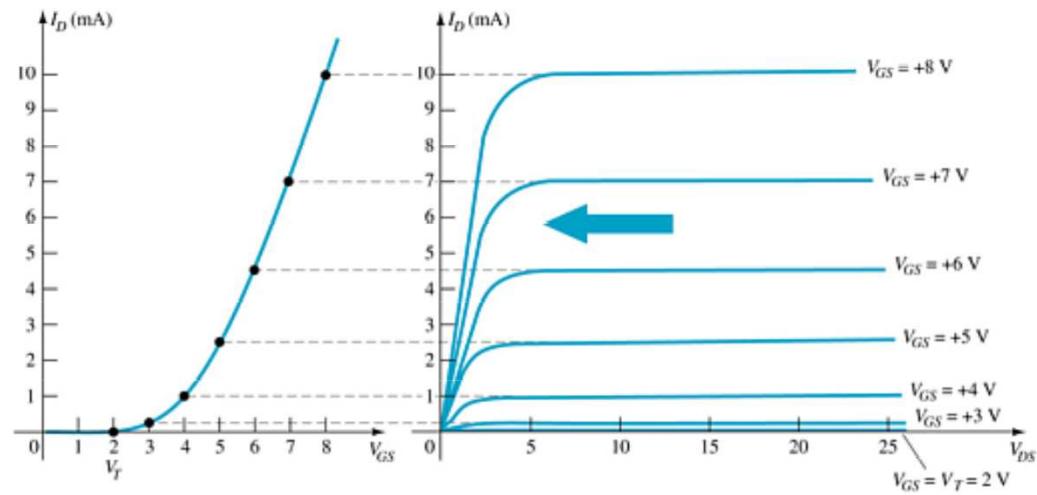
E-Type MOSFET Transfer Curve

To determine I_D given V_{GS} :

$$I_D = k(V_{GS} - V_T)^2$$

Where:

V_T = threshold voltage
or voltage at which the
MOSFET turns on



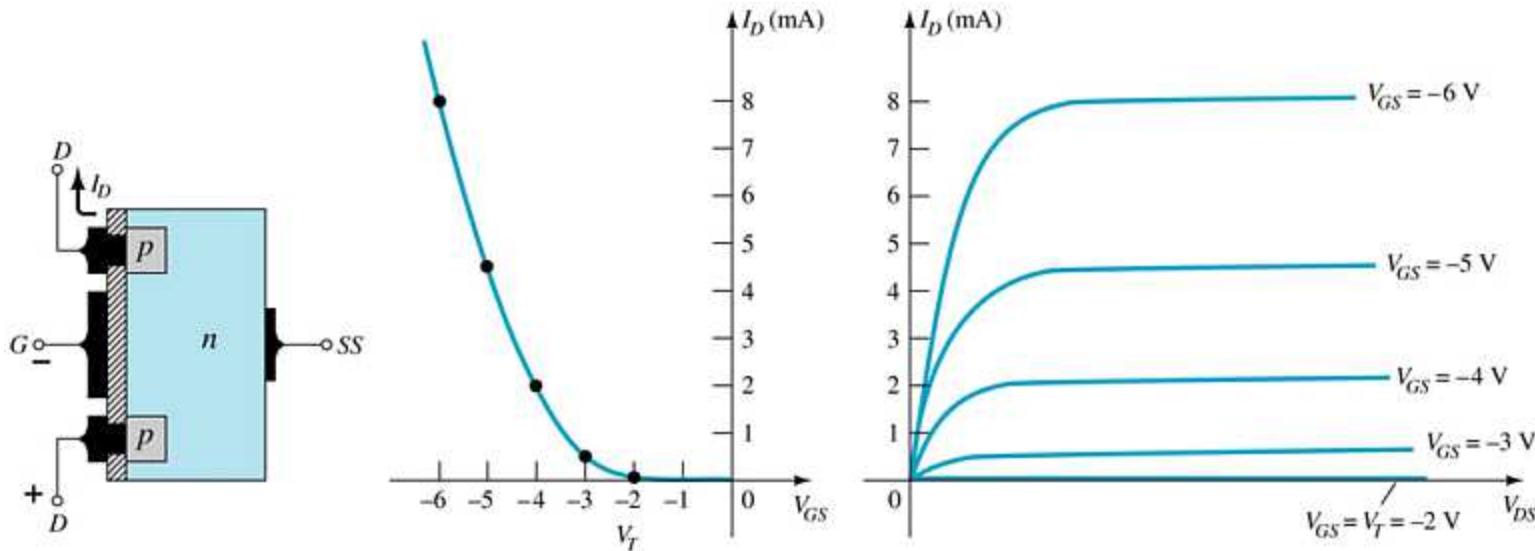
k , a constant, can be determined by using values at a specific point and the formula:

$$k = \frac{I_{D(ON)}}{(V_{GS(ON)} - V_T)^2}$$

V_{Dsat} can be calculated by:

$$V_{Dsat} = V_{GS} - V_T$$

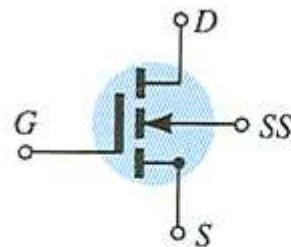
p-Channel E-Type MOSFETs



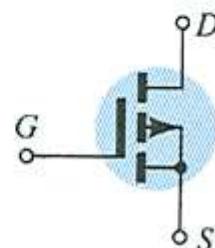
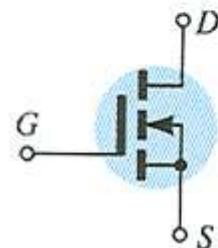
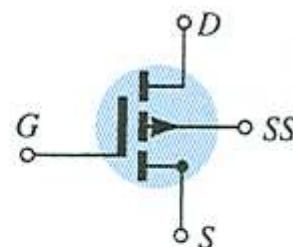
The *p*-channel enhancement-type MOSFET is similar to the *n*-channel, except that the voltage polarities and current directions are reversed.

MOSFET Symbols

n-channel



p-channel



Specification Sheet

Maximum Ratings

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|-----------|-------------|----------------------------|
| Drain-Source Voltage | V_{DS} | 25 | Vdc |
| Drain-Gate Voltage | V_{DG} | 30 | Vdc |
| Gate-Source Voltage* | V_{GS} | 30 | Vdc |
| Drain Current | I_D | 30 | mAdc |
| Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 300 1.7 | mW mW/ $^\circ\text{C}$ |
| Junction Temperature Range | T_J | 175 | $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | -65 to +175 | $^\circ\text{C}$ |

* Transient potentials of ± 75 Volts will not cause gate-oxide failure.



more...

Specification Sheet

Electrical Characteristics

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

| Characteristic | Symbol | Min | Max | Unit |
|---|---------------------|------|----------|-------------------------|
| OFF CHARACTERISTICS | | | | |
| Drain-Source Breakdown Voltage ($I_D = 10 \mu\text{A}$, $V_{GS} = 0$) | $V_{(BR)DSX}$ | 25 | — | Vdc |
| Zero-Gate-Voltage Drain Current ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$) $T_A = 25^\circ\text{C}$ $T_A = 150^\circ\text{C}$ | I_{DSS} | — | 10 10 | nAdc μAdc |
| Gate Reverse Current ($V_{GS} = \pm 15 \text{ Vdc}$, $V_{DS} = 0$) | I_{GSS} | — | ± 10 | pAdc |
| ON CHARACTERISTICS | | | | |
| Gate Threshold Voltage ($V_{DS} = 10 \text{ V}$, $I_D = 10 \mu\text{A}$) | $V_{GS(\text{Th})}$ | 1.0 | 5 | Vdc |
| Drain-Source On-Voltage ($I_D = 2.0 \text{ mA}$, $V_{GS} = 10 \text{ V}$) | $V_{DS(on)}$ | — | 1.0 | V |
| On-State Drain Current ($V_{GS} = 10 \text{ V}$, $V_{DS} = 10 \text{ V}$) | $I_{D(on)}$ | 3.0 | — | mAdc |
| SMALL-SIGNAL CHARACTERISTICS | | | | |
| Forward Transfer Admittance ($V_{DS} = 10 \text{ V}$, $I_D = 2.0 \text{ mA}$, $f = 1.0 \text{ kHz}$) | $ y_{fs} $ | 1000 | — | μmho |
| Input Capacitance ($V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 140 \text{ kHz}$) | C_{iss} | — | 5.0 | pF |
| Reverse Transfer Capacitance ($V_{DS} = 0$, $V_{GS} = 0$, $f = 140 \text{ kHz}$) | C_{trs} | — | 1.3 | pF |
| Drain-Substrate Capacitance ($V_{DSUB} = 10 \text{ V}$, $f = 140 \text{ kHz}$) | C_{dssub} | — | 5.0 | pF |
| Drain-Source Resistance ($V_{GS} = 10 \text{ V}$, $I_D = 0$, $f = 1.0 \text{ kHz}$) | $r_{ds(on)}$ | — | 300 | ohms |
| SWITCHING CHARACTERISTICS | | | | |
| Turn-On Delay (Fig. 5) | t_{dt} | — | 45 | ns |
| Rise Time (Fig. 6) | t_r | — | 65 | ns |
| Turn-Off Delay (Fig. 7) | t_{d2} | — | 60 | ns |
| Fall Time (Fig. 8) | t_f | — | 100 | ns |
| $I_D = 2.0 \text{ mAdc}$, $V_{DS} = 10 \text{ Vdc}$, $(V_{GS} = 10 \text{ Vdc})$ (See Figure 9; Times Circuit Determined) | | | | |

Handling MOSFETs

MOSFETs are very sensitive to static electricity. Because of the very thin SiO_2 layer between the external terminals and the layers of the device, any small electrical discharge can create an unwanted conduction.

Protection

- Always transport in a static sensitive bag
- Always wear a static strap when handling MOSFETs
-
- Apply voltage limiting devices between the gate and source, such as back-to-back Zeners to limit any transient voltage.

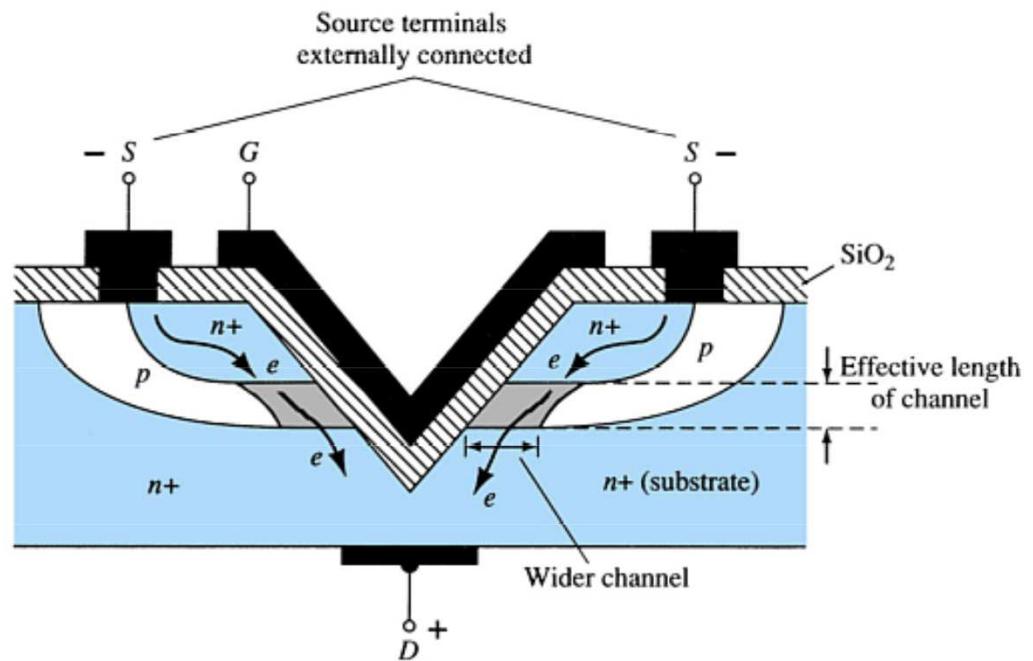


VMOS Devices

VMOS (vertical MOSFET)
increases the surface area of
the device.

Advantages

- VMOS devices handle higher currents by providing more surface area to dissipate the heat.
- VMOS devices also have faster switching times.

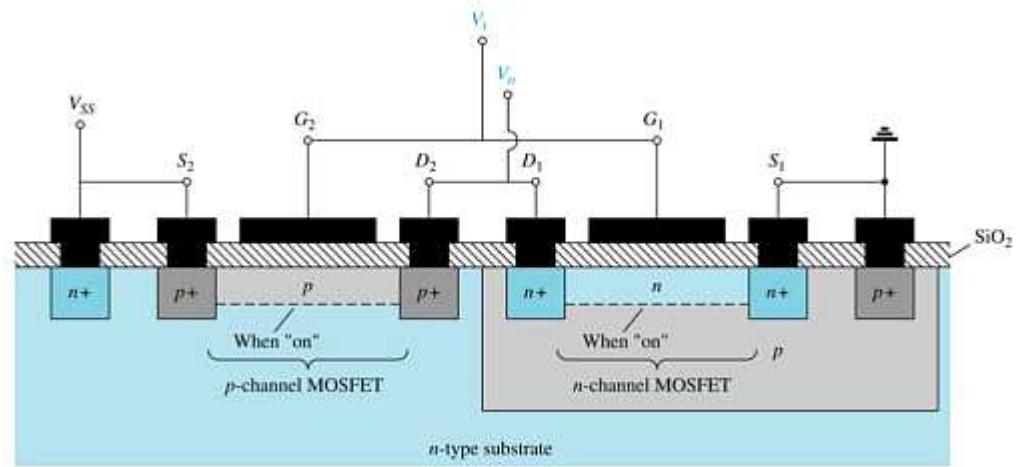


CMOS Devices

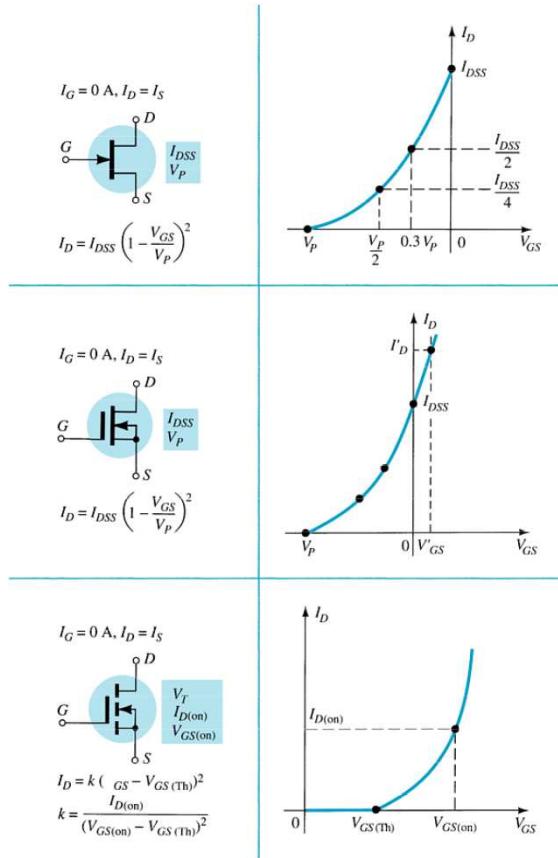
CMOS (complementary MOSFET) uses a *p*-channel and *n*-channel MOSFET; often on the same substrate as shown here.

Advantages

- Useful in logic circuit designs
- Higher input impedance
- Faster switching speeds
- Lower operating power levels



Summary Table



Common FET Biasing Circuits

JFET Biasing Circuits

- Fixed – Bias
- Self-Bias
- Voltage-Divider Bias

D-Type MOSFET Biasing Circuits

- Self-Bias
- Voltage-Divider Bias

E-Type MOSFET Biasing Circuits

- Feedback Configuration
- Voltage-Divider Bias



Basic Current Relationships

For all FETs:

$$I_G \approx 0A$$

$$I_D = I_S$$

For JFETs and D-Type MOSFETs:

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

For E-Type MOSFETs:

$$I_D = k(V_{GS} - V_T)^2$$



Fixed-Bias Configuration

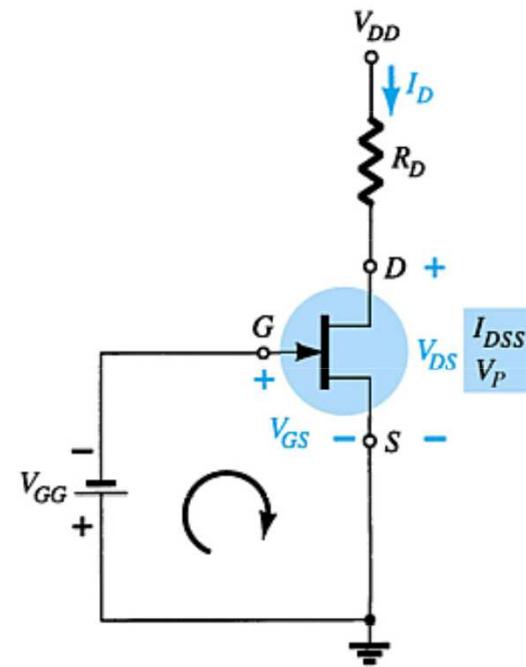
$$V_{DS} = V_{DD} - I_D R_D$$

$$V_S = 0V$$

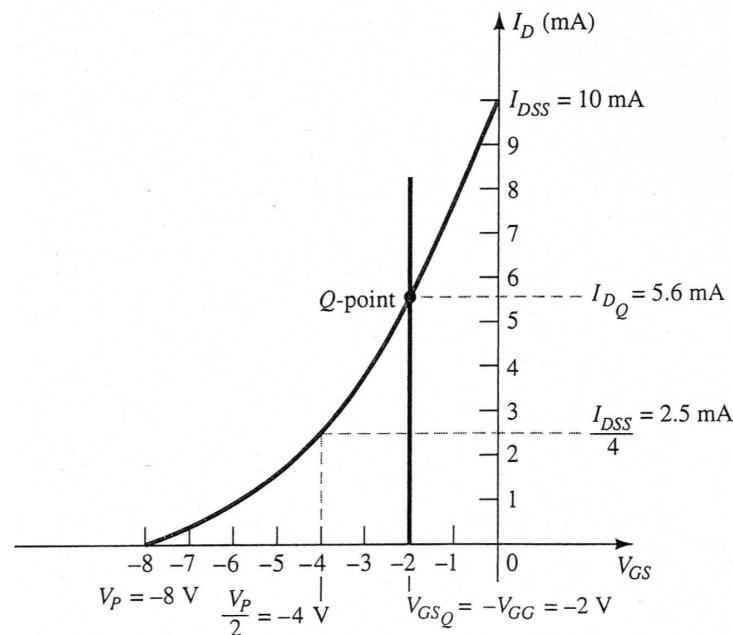
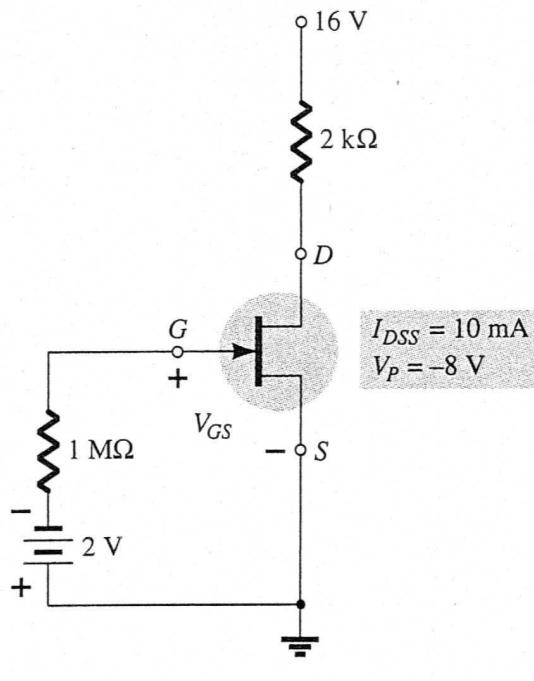
$$V_C = V_{DS}$$

$$V = V_{GS}$$

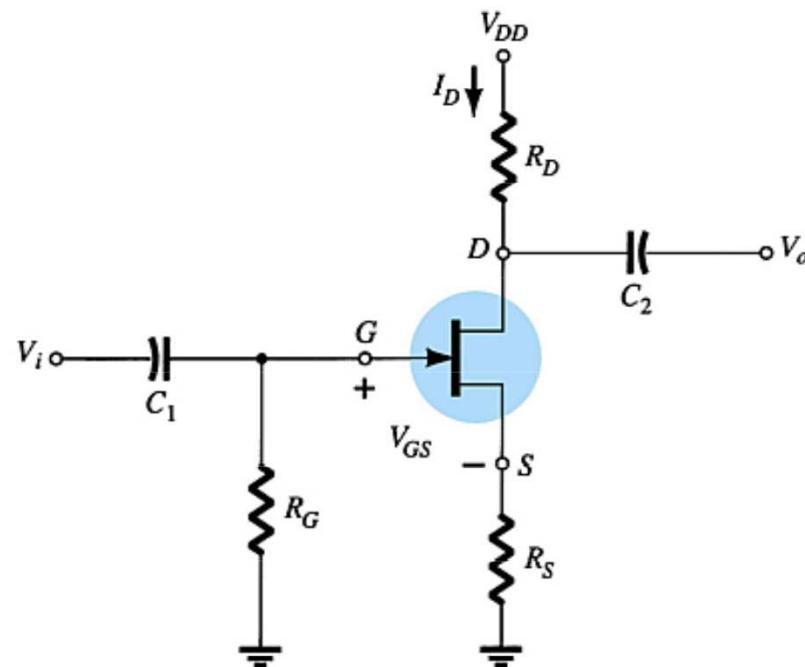
$$V_{GS} = -V_{GG}$$



Fixed-Bias Configuration



Self-Bias Configuration



Self-Bias Calculations

For the indicated loop, $V_{GS} = -I_D R_S$

To solve this equation:

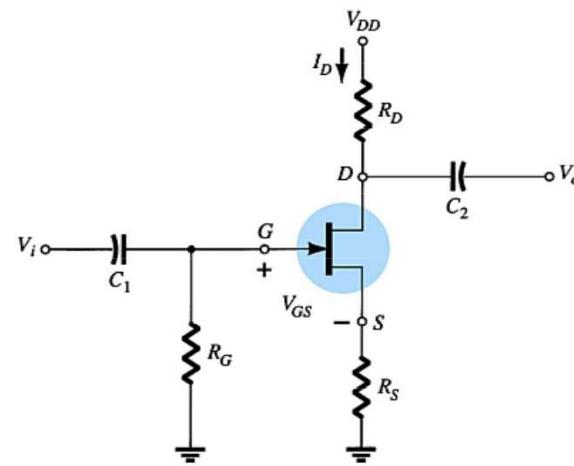
- Select an $I_D < I_{DSS}$ and use the component value of R_S to calculate V_{GS}
- Plot the point identified by I_D and V_{GS} . Draw a line from the origin of the axis to this point.
- Plot the transfer curve using I_{DSS} and V_P ($V_P = V_{GSoff}$ in specification sheets) and a few points such as $I_D = I_{DSS}/4$ and $I_D = I_{DSS}/2$ etc.

The Q-point is located where the first line intersects the transfer curve. Use the value of I_D at the Q-point (I_{DQ}) to solve for the other voltages:

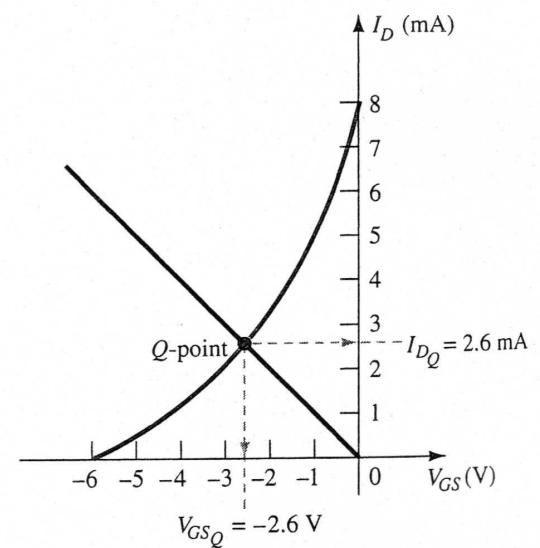
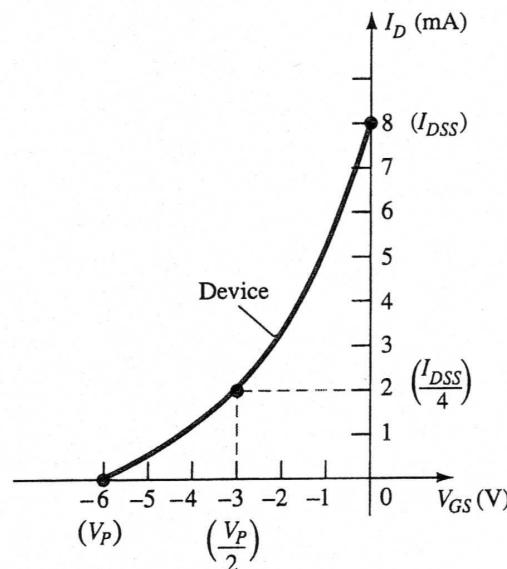
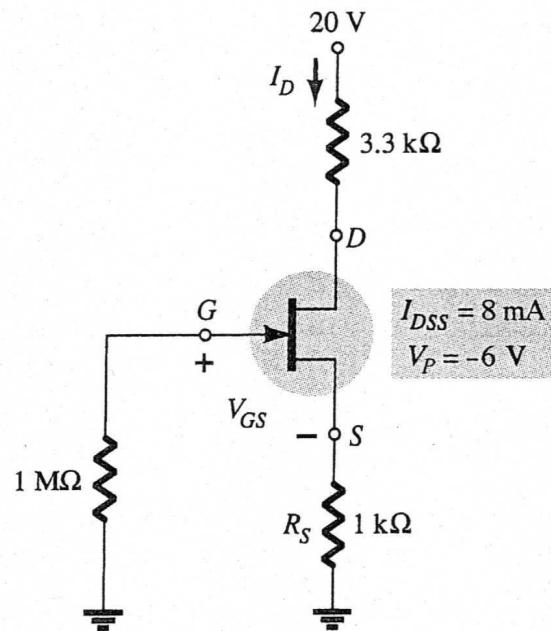
$$V_{DS} = V_{DD} - I_D(R_S + R_D)$$

$$V_S = I_D R_S$$

$$V_D = V_{DS} + V_S = V_{DD} - V_{RD}$$



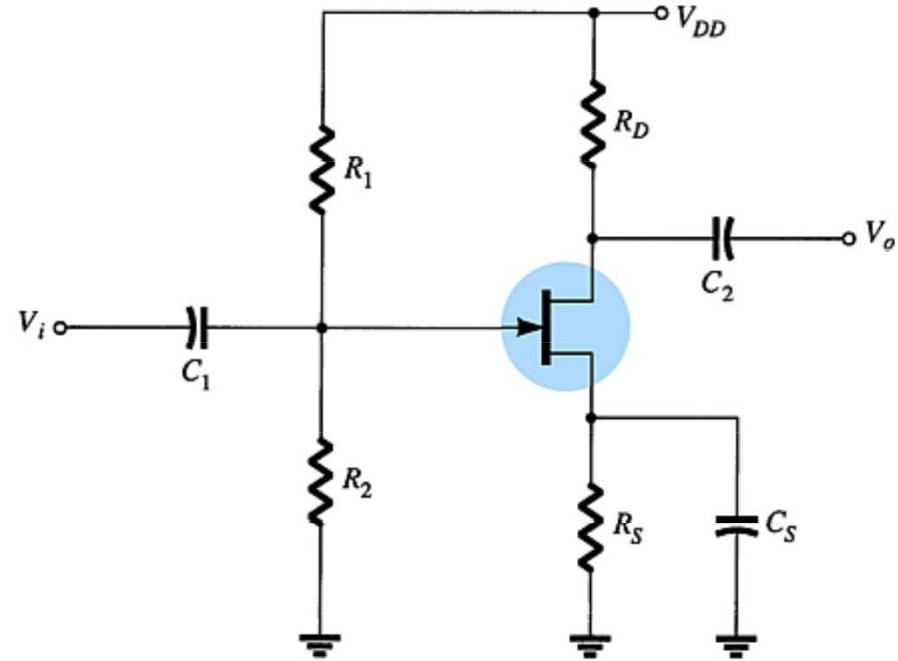
Self-Bias Configuration



Voltage-Divider Bias

$I_G = 0 \text{ A}$

I_D responds to changes in
 V_{GS} .



Voltage-Divider Bias Calculations

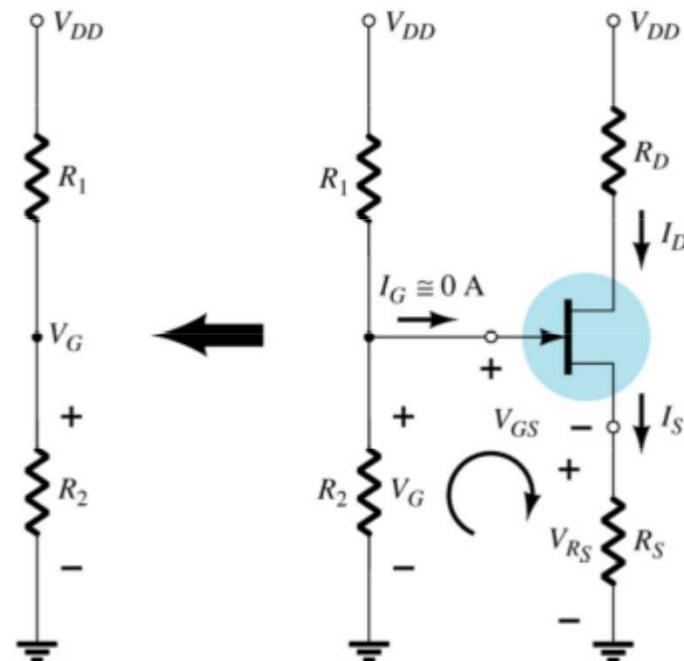
V_G is equal to the voltage across divider resistor R_2 :

$$V_G = \frac{R_2 V_{DD}}{R_1 + R_2}$$

Using Kirchhoff's Law:

$$V_{GS} = V_G - I_D R_S$$

The Q point is established by plotting a line that intersects the transfer curve.



Voltage-Divider Q-point

Step 1

Plot the line by plotting two points:

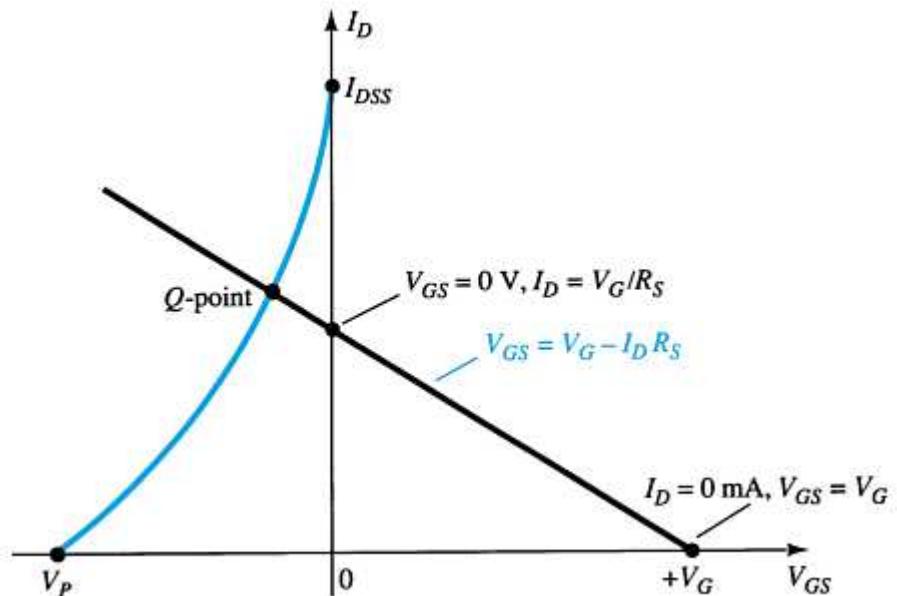
- $V_{GS} = V_G, I_D = 0 \text{ A}$
- $V_{GS} = 0 \text{ V}, I_D = V_G / R_S$

Step 2

Plot the transfer curve by plotting I_{DSS} , V_P and the calculated values of I_D

Step 3

The Q-point is located where the line intersects the transfer curve



Voltage-Divider Bias Calculations

Using the value of I_D at the Q-point, solve for the other variables in the voltage-divider bias circuit:

$$V_{DS} = V_{DD} - I_D(R_D + R_S)$$

$$V_D = V_{DD} - I_D R_D$$

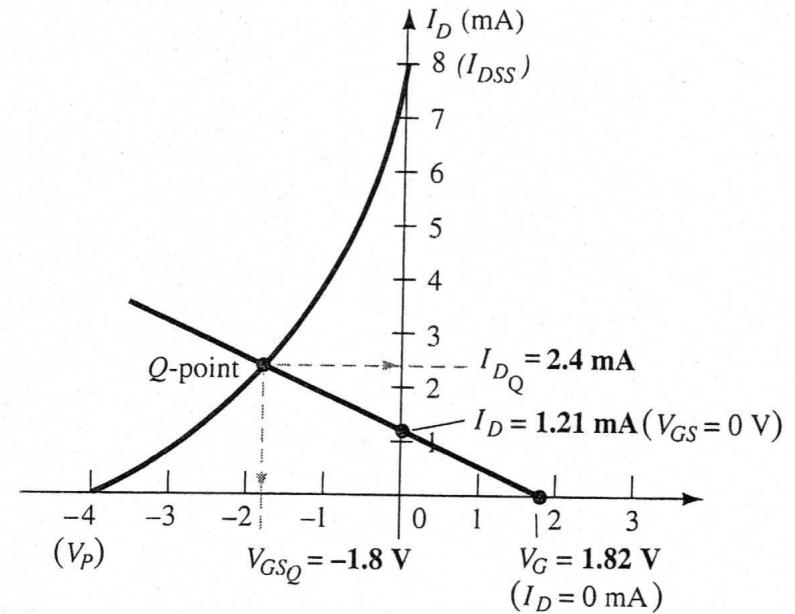
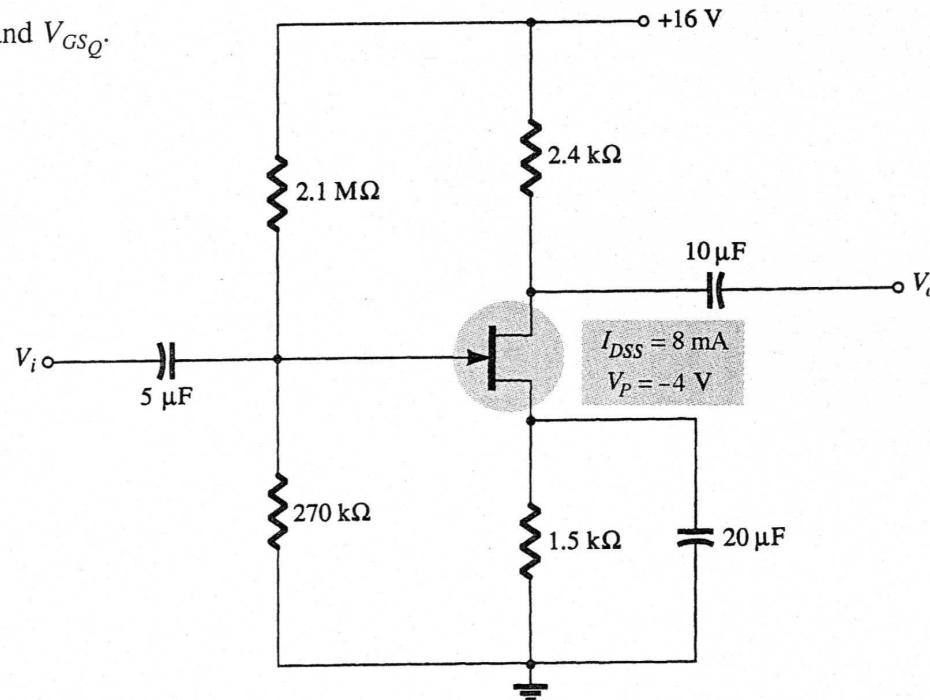
$$V_S = I_D R_S$$

$$I_{R1} = I_{R2} = \frac{V_{DD}}{R_1 + R_2}$$



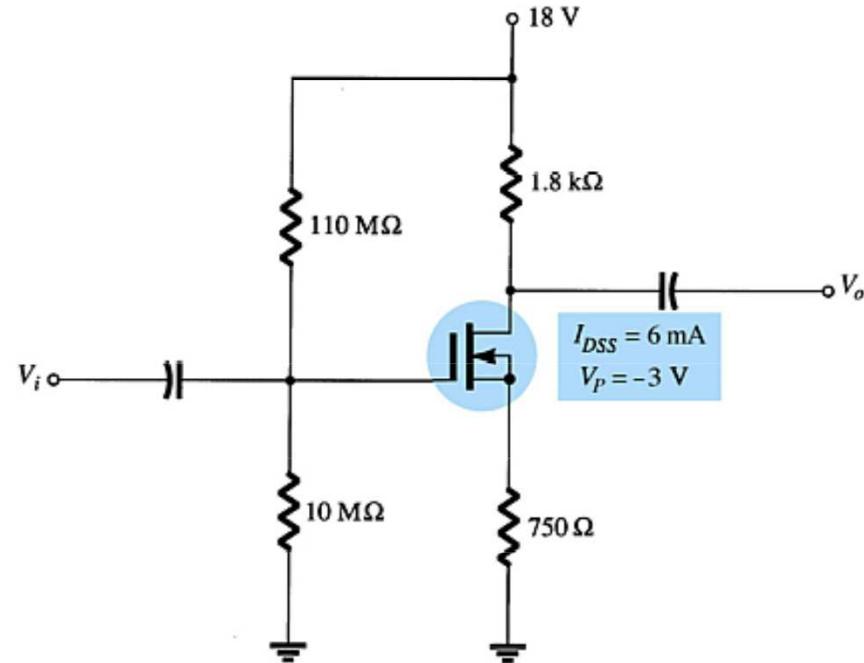
Voltage-Divider Bias Calculations

- a. I_{DQ} and V_{GSQ} .
- b. V_D .
- c. V_S .
- d. V_{DS} .
- e. V_{DG} .



D-Type MOSFET Bias Circuits

Depletion-type MOSFET bias circuits are similar to those used to bias JFETs. The only difference is that depletion-type MOSFETs can operate with positive values of V_{GS} and with I_D values that exceed I_{DSS} .



Self-Bias

Step 1

Plot line for

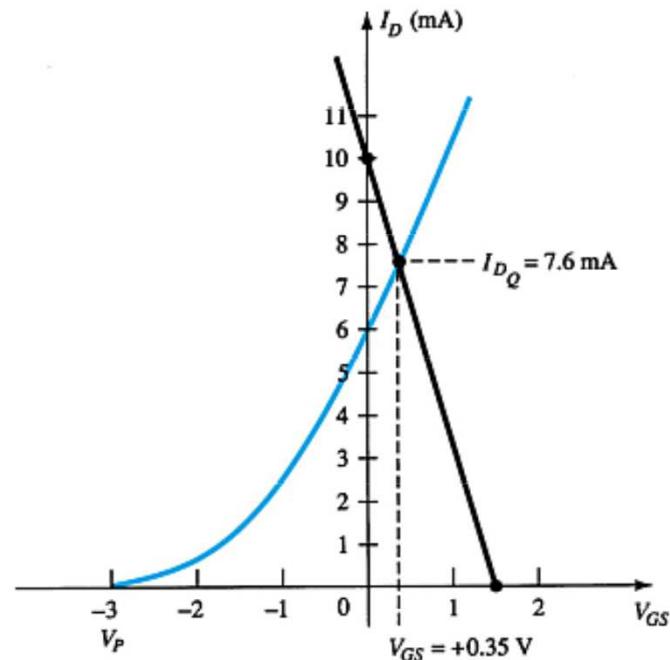
$$V_{GS} = -I_D R_S$$

Step 2

Plot the transfer curve using I_{DSS} , V_P and calculated values of I_D

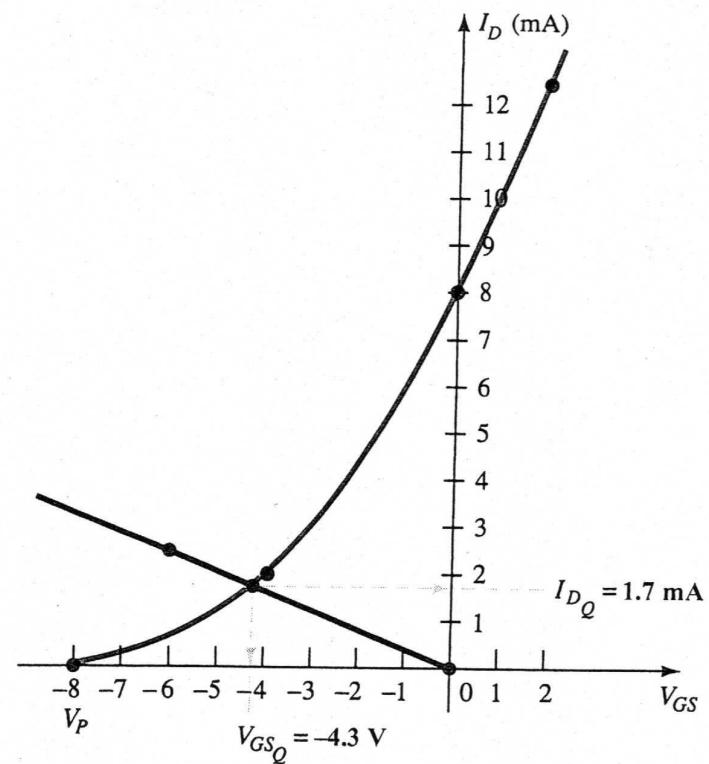
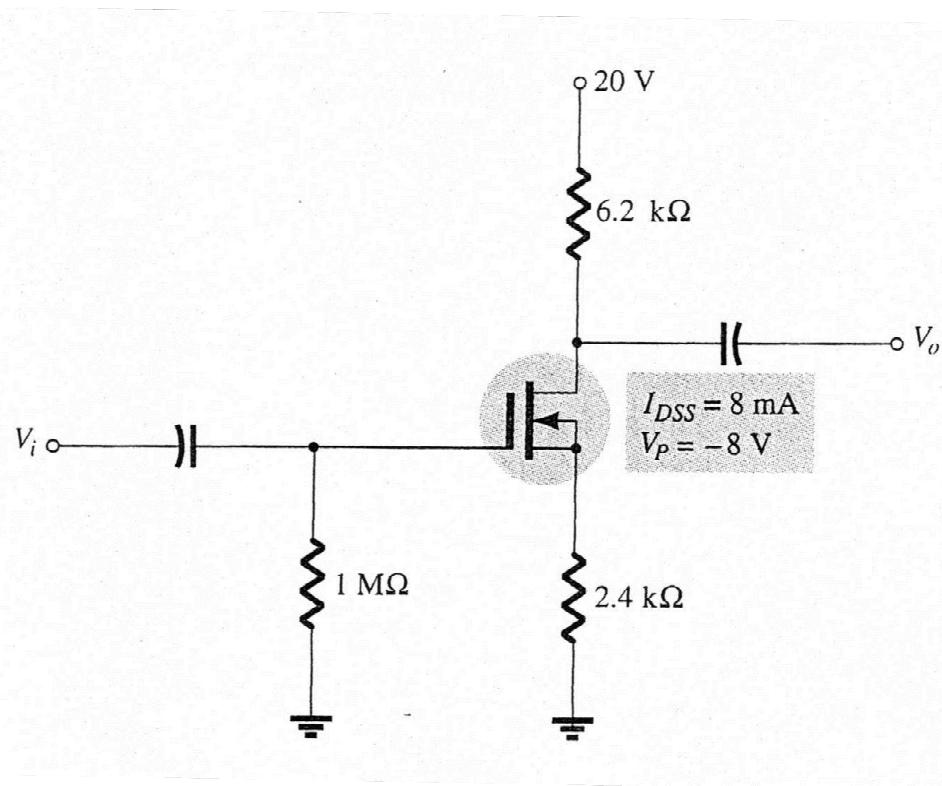
Step 3

The Q-point is located where the line intersects the transfer curve. Use the I_D at the Q-point to solve for the other variables in the voltage-divider bias circuit.



These are the same steps used to analyze JFET self-bias circuits.

Self-Bias



Voltage-Divider Bias

Step 1

Plot the line for

- $V_{GS} = V_G, I_D = 0 \text{ A}$
- $I_D = V_G/R_S, V_{GS} = 0 \text{ V}$

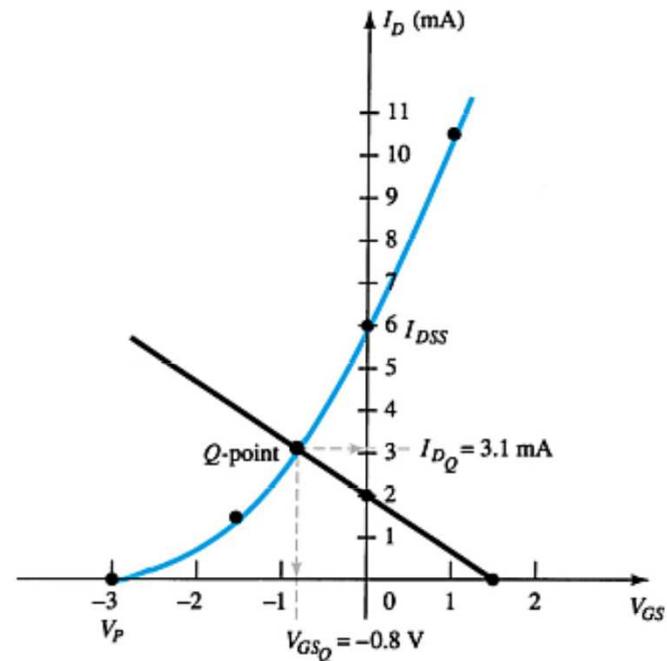
Step 2

Plot the transfer curve using I_{DSS} , V_P and calculated values of I_D .

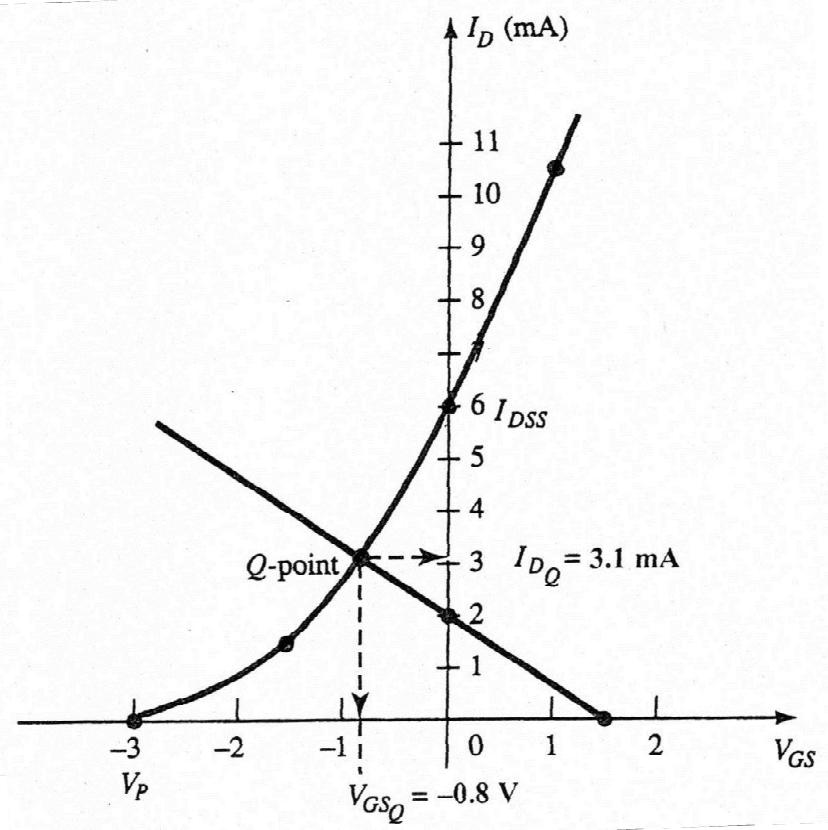
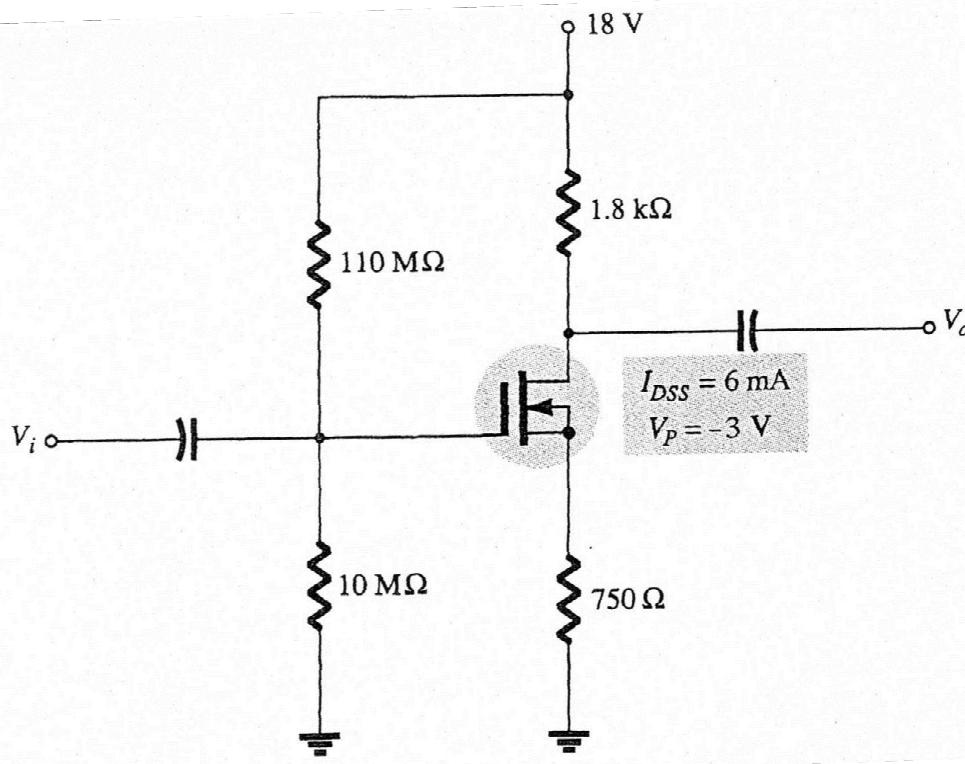
Step 3

The Q-point is located where the line intersects the transfer curve is. Use the I_D at the Q-point to solve for the other variables in the voltage-divider bias circuit.

These are the same steps used to analyze JFET voltage-divider bias circuits.

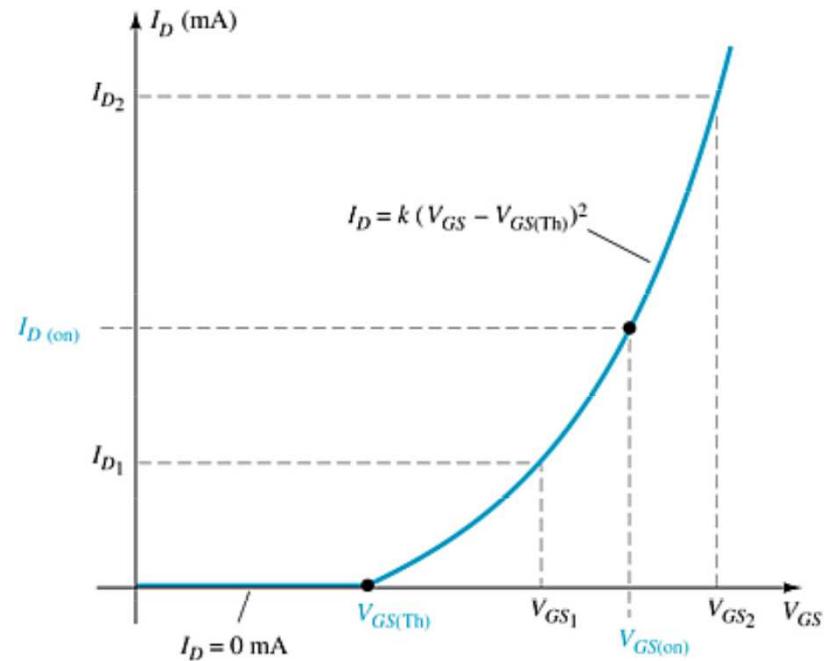


Voltage-Divider Bias



E-Type MOSFET Bias Circuits

The transfer characteristic for the e-type MOSFET is very different from that of a simple JFET or the d-type MOSFET.



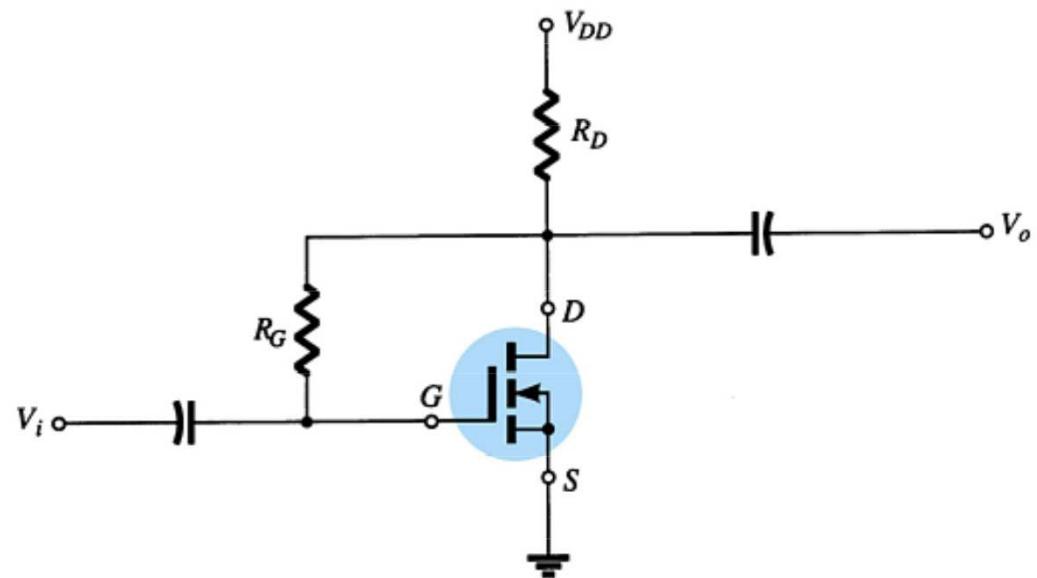
Feedback Bias Circuit

$$I_G = 0 \text{ A}$$

$$V_{RG} = 0 \text{ V}$$

$$V_{DS} = V_{GS}$$

$$V_{GS} = V_{DD} - I_D R_D$$



Feedback Bias Q-Point

Step 1

Plot the line using

- $V_{GS} = V_{DD}$, $I_D = 0 \text{ A}$
- $I_D = V_{DD} / R_D$, $V_{GS} = 0 \text{ V}$

Step 2

Using values from the specification sheet, plot the transfer curve with

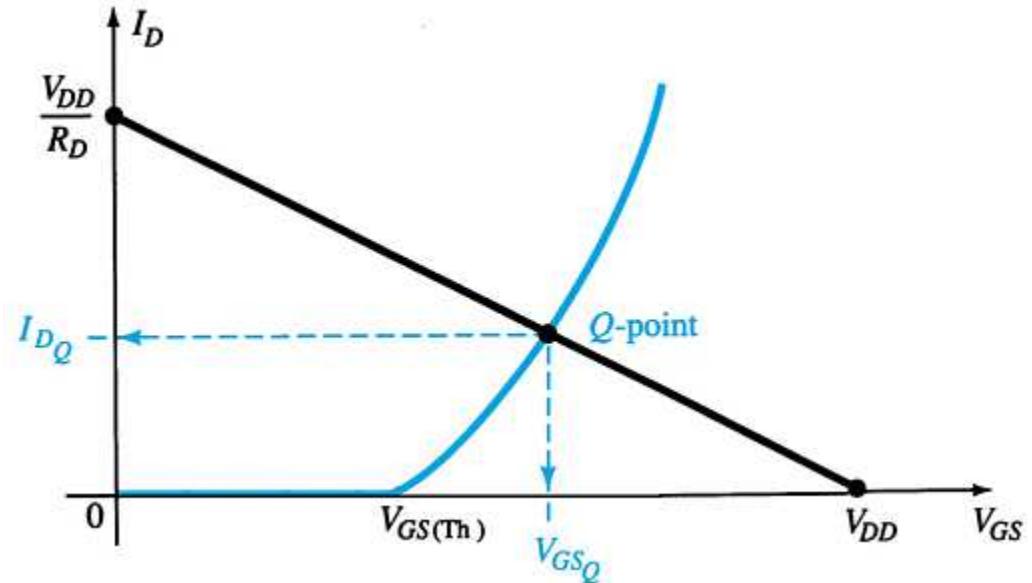
- V_{GSTh} , $I_D = 0 \text{ A}$
- $V_{GS(on)}$, $I_{D(on)}$

Step 3

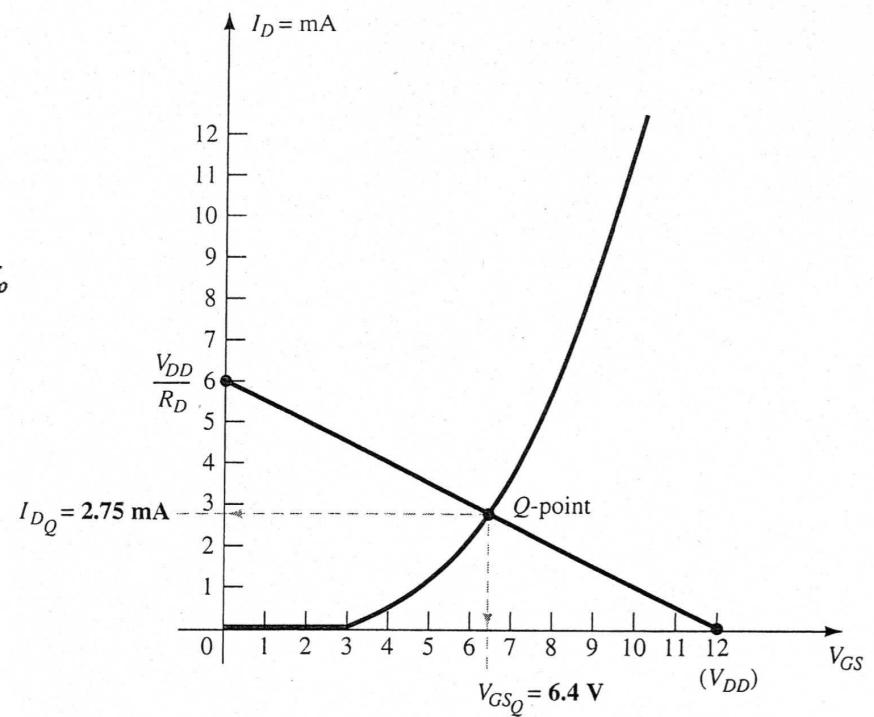
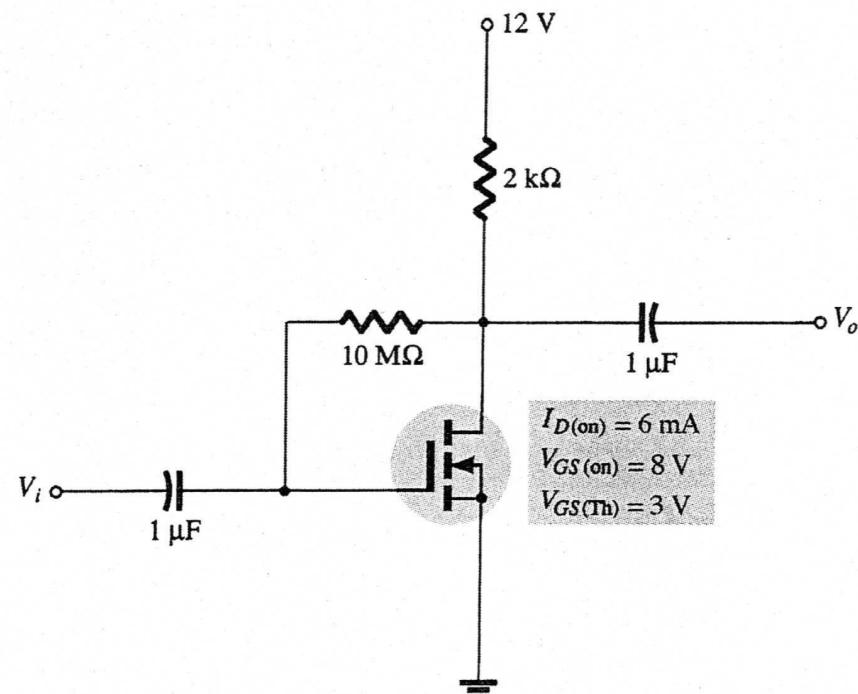
The Q-point is located where the line and the transfer curve intersect

Step 4

Using the value of I_D at the Q-point, solve for the other variables in the bias circuit



Feedback Bias Circuit



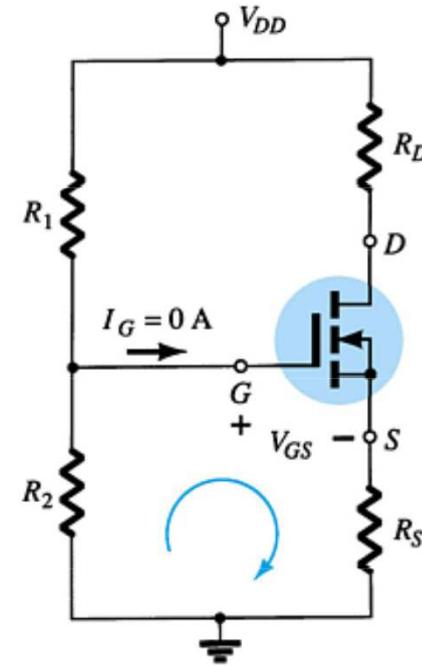
Voltage-Divider Biasing

Plot the line and the transfer curve to find the Q-point. Use these equations:

$$V_G = \frac{R_2 V_{DD}}{R_1 + R_2}$$

$$V_{GS} = V_G - I_D R_S$$

$$V_{DS} = V_{DD} - I_D (R_S + R_D)$$



Voltage-Divider Bias Q-Point

Step 1

Plot the line using

- $V_{GS} = V_G = (R_2 V_{DD}) / (R_1 + R_2)$, $I_D = 0 \text{ A}$
- $I_D = V_G/R_S$, $V_{GS} = 0 \text{ V}$

Step 2

Using values from the specification sheet, plot the transfer curve with

- V_{GSTh} , $I_D = 0 \text{ A}$
- $V_{GS(on)}$, $I_{D(on)}$

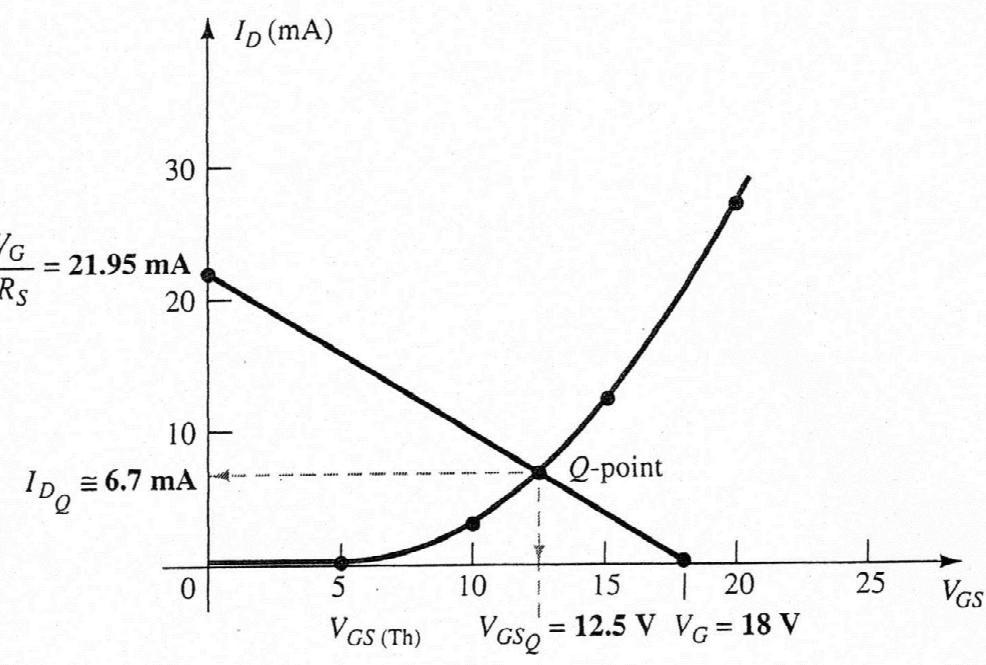
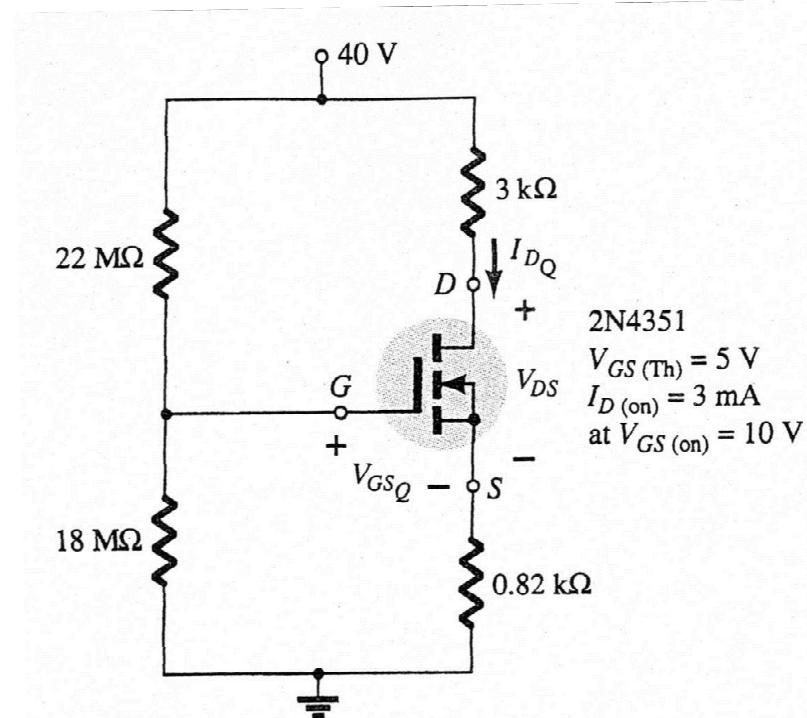
Step 3

The point where the line and the transfer curve intersect is the Q-point.

Step 4

Using the value of I_D at the Q-point, solve for the other circuit values.

Voltage-Divider Biasing



p-Channel FETs

For *p*-channel FETs the same calculations and graphs are used, except that the voltage polarities and current directions are reversed.

The graphs are mirror images of the *n*-channel graphs.



Applications

**Voltage-controlled resistor
JFET voltmeter
Timer network
Fiber optic circuitry
MOSFET relay driver**



Homework 4 (Chapter 6)

- Transfer Characteristics
 - 6.3 (11, 12)
- Depletion-Type MOSFET
 - 6.7 (28)
- Enhancement-Type MOSFET
 - 6.8 (33, 36)



Homework 4 (Chapter 7)

- **Fixed-biased**
 - **7.2 (1)**
- **Self-biased**
 - **7.3 (6)**
- **Voltage-Divider**
 - **7.4 (12)**
- **Depletion-Type**
 - **7.5 (18)**
- **Enhancement-Type**
 - **7.6 (20)**